RZ/N2L Group

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RZ/N2L Industrial Network SOM Kit Application Note: EtherCAT Slave Software

Introduction

This document explains Sample Program setup procedures for EtherCAT® slave functionalities with the adapted EtherCAT Stack Code for Renesas RZ/N2L platform. This describes steps to confirm slave behavior and stack features using TwinCAT®Master Configuration tool.

Target Device

RZ/N2L

Contents

1. Overview

This document describes how to run EtherCAT on the RZ/N2L Group. Run the standalone variant using only one core.

EtherCAT(Ethernet for Control Automation Technology) is an Ethernet based fieldbus system, developed by Beckhoff Automation. Development of EtherCAT was to apply Ethernet for automation applications (e.g., for motion control, I/O, sensors) requiring short data update times with low communication jitter and reduced hardware costs.

Tool to generate EtherCAT Slave Stack Code (SSC Tool) is available to the ETG members free of charge. This can be downloaded from the ETG website. SSC tool can be used to generate customized stack, device description files (ESI) and individual source code documentation to suit the developer's own needs.

This document describes the procedure for testing the EtherCAT slave function using EtherCAT stack code compatible with the Renesas RZ/N2L platform. Scope of the documentation is limited to explaining how to use the SSC tool for EtherCAT slave stack code generation and testing its behavior against TwinCAT masters and test applications.

1.1 Abbreviations/Definitions

Table 1. Abbreviations/Definitions

Index	Abbreviations /Definitions	Description
1	CoE	CAN application protocol over EtherCAT
2	EEPROM	Electrically Erasable Programmable Read-Only Memory
3	ESC	EtherCAT Slave Controller
4	ESI	EtherCAT Slave Information
5	FoE	File Access Over EtherCAT
6	I2C	Inter-Integrated Circuit
7	MB	Mailbox
8	PDO	Process Data Object
9	SSC	Slave Stack Code
10	EoE	Ethernet Over EtherCAT

1.2 Reference

Technical information about EtherCAT is available via ETG member site, and information about RZ/N2L is available via Renesas.

Table 2. Technical Inputs

Index	Technical Inputs
1	r01uh0955ejxxxx-rzn2l.pdf (RZ/N2L User's Manual: Hardware)
2	r01an6434ejxxxx-rzt2-rzn2-fsp-getting-started.pdf (Getting started with Flexible Software Package)
3	r12ut0020edxxxx-rzn2l-som-kit-hw.pdf (RZ/N2L Industrial Network SOM Kit Use's Manual)

2. Features

EtherCAT slave stack code generated by SSC Tool provides the functionality of EtherCAT slave controller.

Includes the following features:

- ESM (EtherCAT State Machine)
- Mailbox protocols:
  - CoE (CAN application protocol over EtherCAT)
- Synchronization Modes:
  - Free Run
  - Sync Manager Synchronization
  - DC Synchronization
- I/O function:
  - I/O Input DIP SW
  - I/O Output LED

3. Project Setup

3.1 Requirements

Table 3. Requirements

Item	Vender	Description
Board	Renesas Electronics	RZ/N2L Industrial Network SOM Kit
IDE	IAR Systems	● Embedded Workbench® for ARM Version 9.30.1 Please apply patch (EWARM_Patch_for_RZN2L) which is available in http://www.renesas.com/rzn2l. Regarding how to apply the patch, please read the readme file in patch file.
	Renesas Electronics	● e² studio 2023-04 ● FSP Smart Configurator 2023-04 ● RZ/N2L Flexible Software Package (FSP) v1.2.0 Please download from the link below. https://github.com/renesas/rzn-fsp/releases/tag/v1.2.0
Emulator	IAR Systems	I-jet
	SEGGER	Hardware: J-Link Software: J-Link Commander V7.82f *1
SSC Tool	Beckhoff Automation	Slave Stack Code (SSC) Tool Version 5.13
Software PLC	Beckhoff Automation	TwinCAT3

*1: J-Link Commander is used for erasing flash memory.
J-Link Commander is included in “J-Link Software and Documentation Pack” on the following site.
https://www.segger.com/downloads/jlink/

3.2 Hardware

This document describes the major hardware. Refer to RZ/N2L Industrial Network SOM Kit user's manual and schematic for more board details.

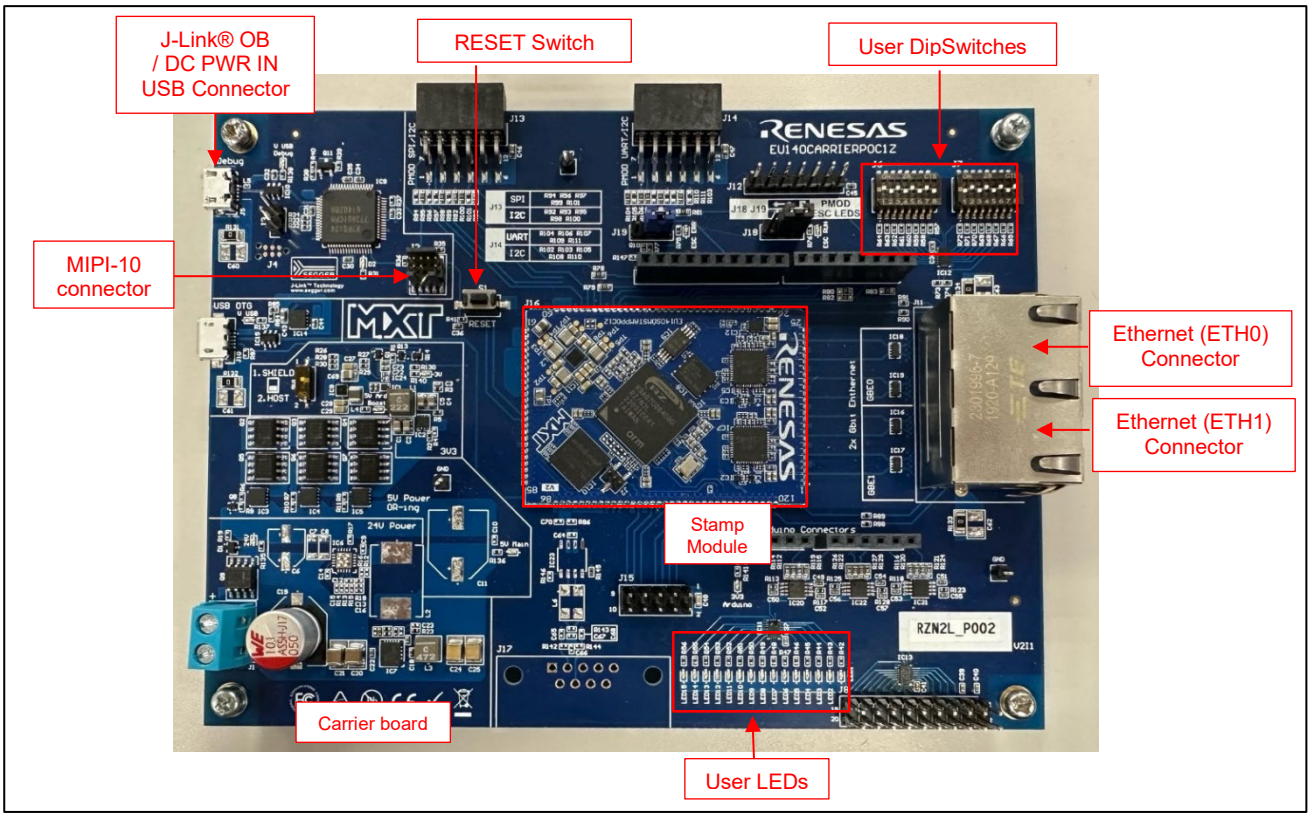


Figure 3-1 RZ/N2L Industrial Network SOM Kit

3.3 Note about Ethernet PHY driver using FSP

This SOM Kit has VSC8531 that is not compatible with FSP as PHY chip. Therefore, we have modified the PHY driver for VSC8531. For details, see "Appendix: FSP Configuration for VSC8531 and SSC port".

3.4 Setup the Board

Setting the board for running sample program is shown below.

1. Connect the I-jet to J2 or the USB cable to J5 for J-link OB on Carrier board.

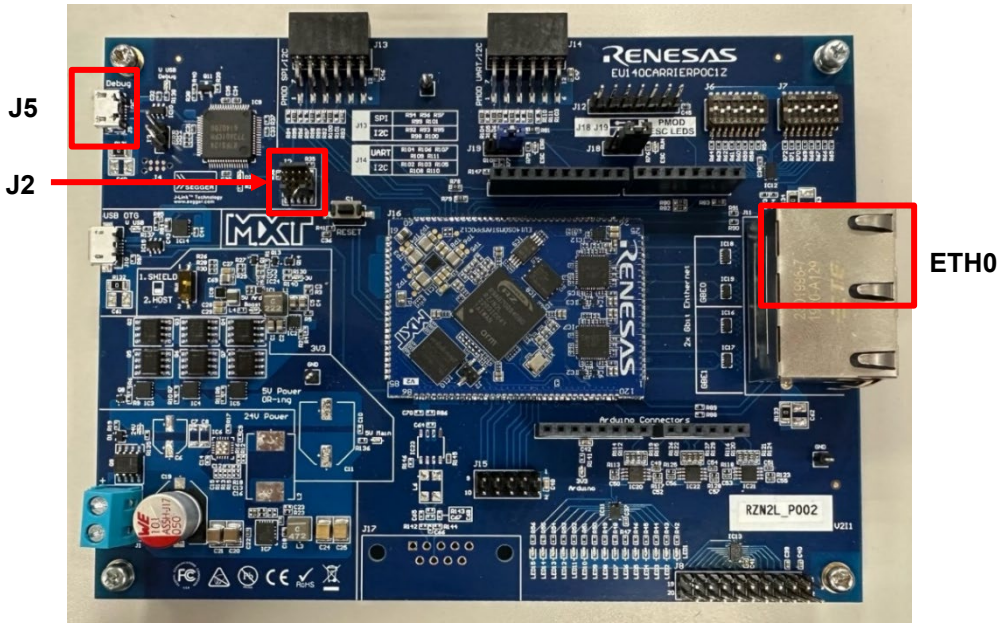


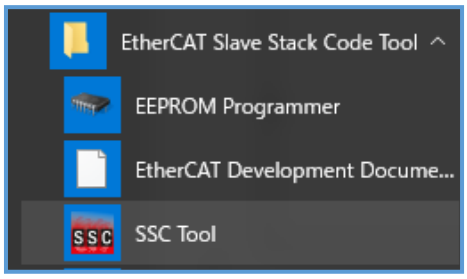
Figure 3-2 Setup the SOM Kit

2. Power is supplied by connecting USB Micro-B cable to the USB connector “J5) of the Carrier board.
3. Connect Ethernet Cable to the Ethernet Connector “ETH0”.

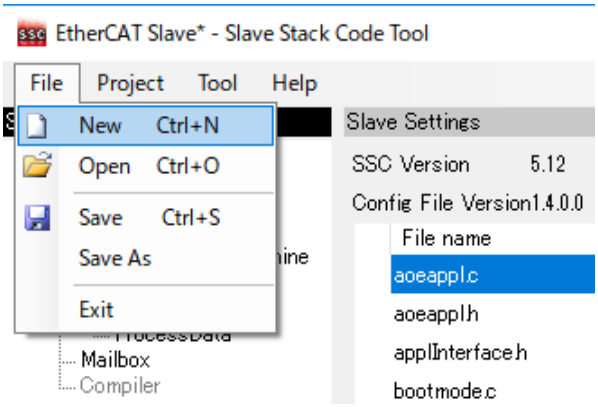
3.5 Generating the Slave Stack Code

SSC Tool is used for generating the slave stack code.
Note). Replace the folder name in the following description according to the tool to be used.

1. Start the SSC Tool from the Window Start menu.

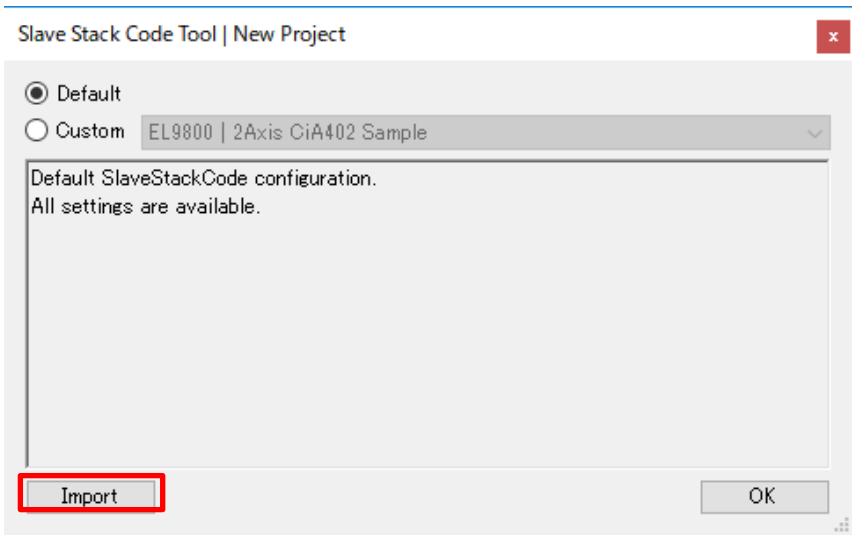


2. Select File > New.

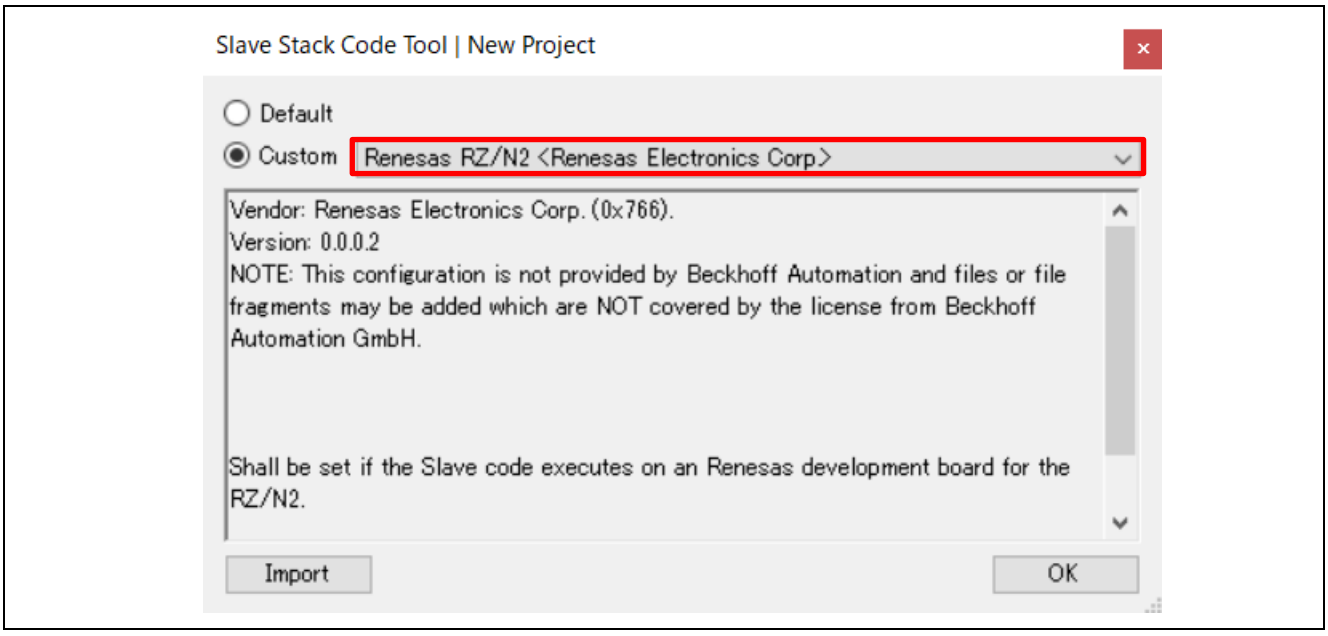


1. Click the [Import] button and select the SSC Tool configuration file at,

"common\ecat_IO\SSCconfig\Renesas_RZN2_config.xml"

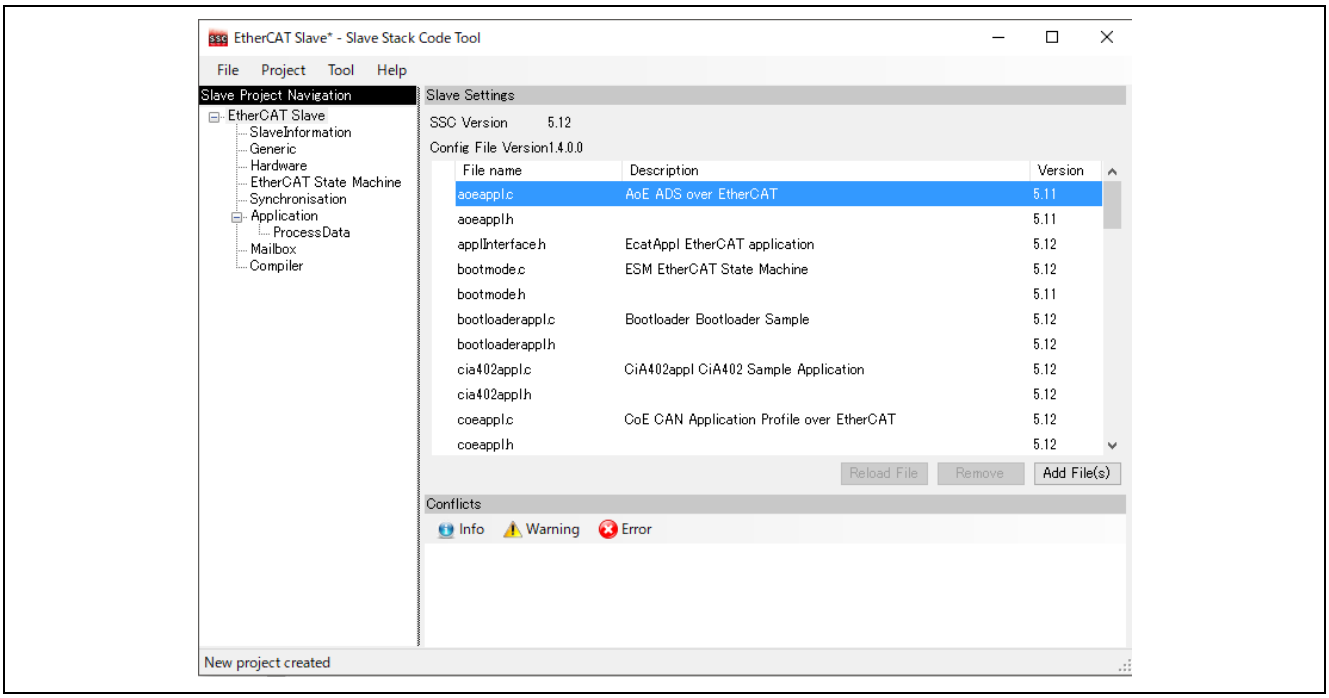


2. After the configuration file is read, the window changes as follows:

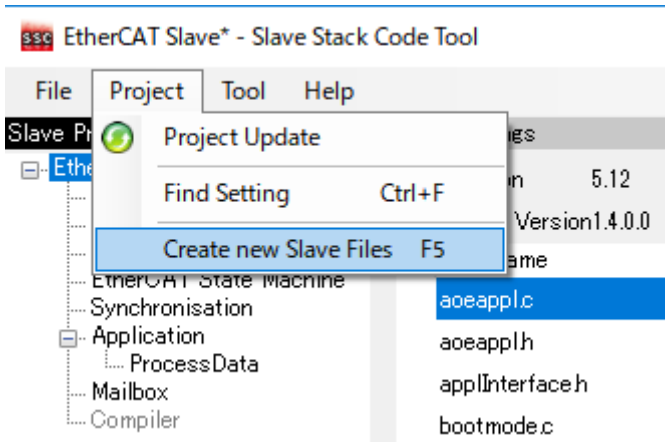


Once the configuration file is read, it is registered in Custom and is selectable from the drop-down list.

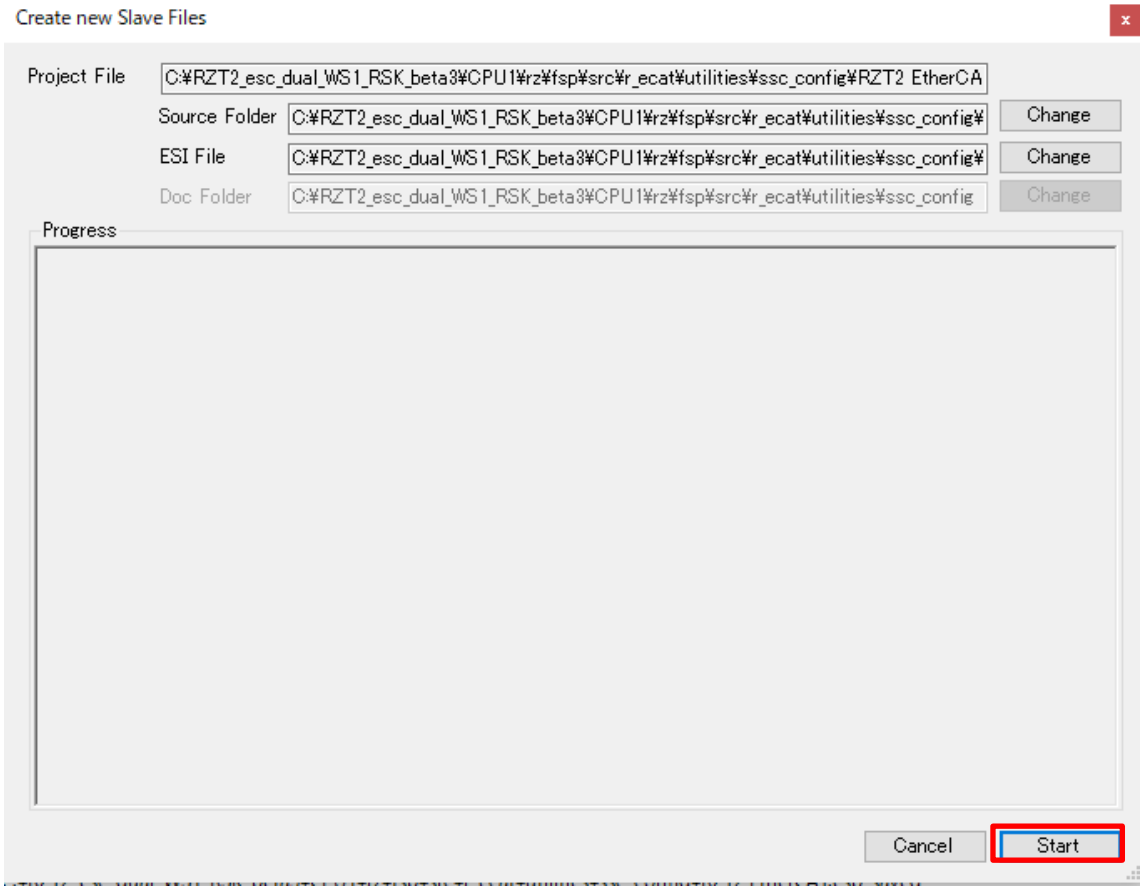
3. After clicking the [OK] button, the following window opens.



4. Select Project > Create new Slave Files.

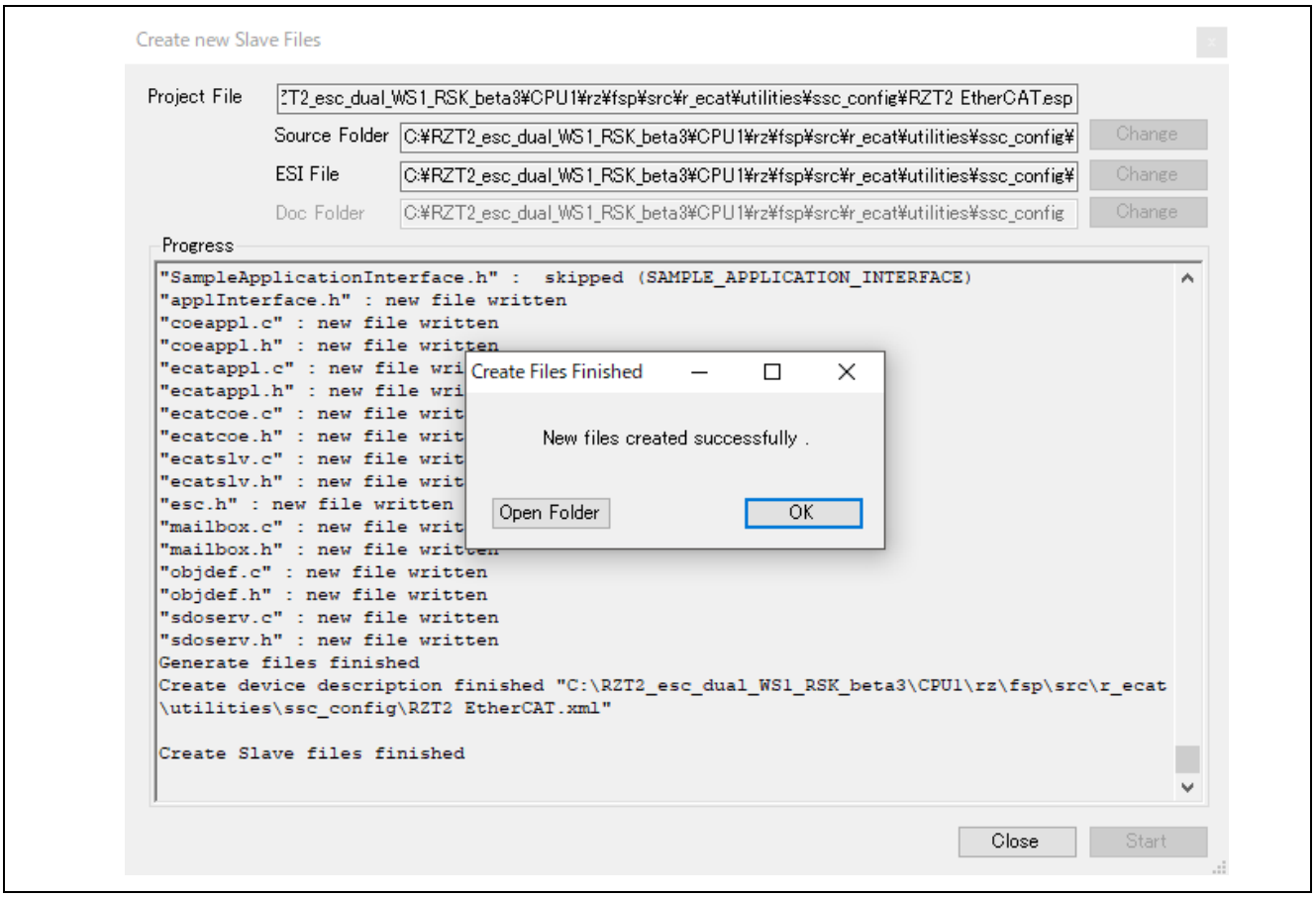


5. Click the [Start] button to start creating the EtherCAT Slave Stack Code.



6. When a message “New file created successfully” appears, the creation processing is completed, and the source files are located in the following folder.

“common\ecat_IO\SSCconfig\Src”



7. Move the generated EtherCAT slave stack code to the EtherCAT application source folder. The sampleappl.c and sampleappl.h are stored in the destination “\application\ecat” folder. When moving the slave stack code to the application folder, be careful not to delete these files. Remove the original Src code (code generated in the Src folder by SSC) from the folder or exclude the Src code from your build target.

Source folder: (code generated in the Src folder by SSC)
“common\ecat_IO\SSCconfig\Src”

Move destination folder:
“project\rzn2l_som\ecat_IO\ewarm (e2studio) \src
ethercat\beckhoff”

4. Setting up a TwinCAT3

4.1 Copying the ESI Files

Before starting TwinCAT, copy the ESI files that are included in the release folder to TwinCAT destination "\TwinCAT\3.x\Config\IO\EtherCAT"

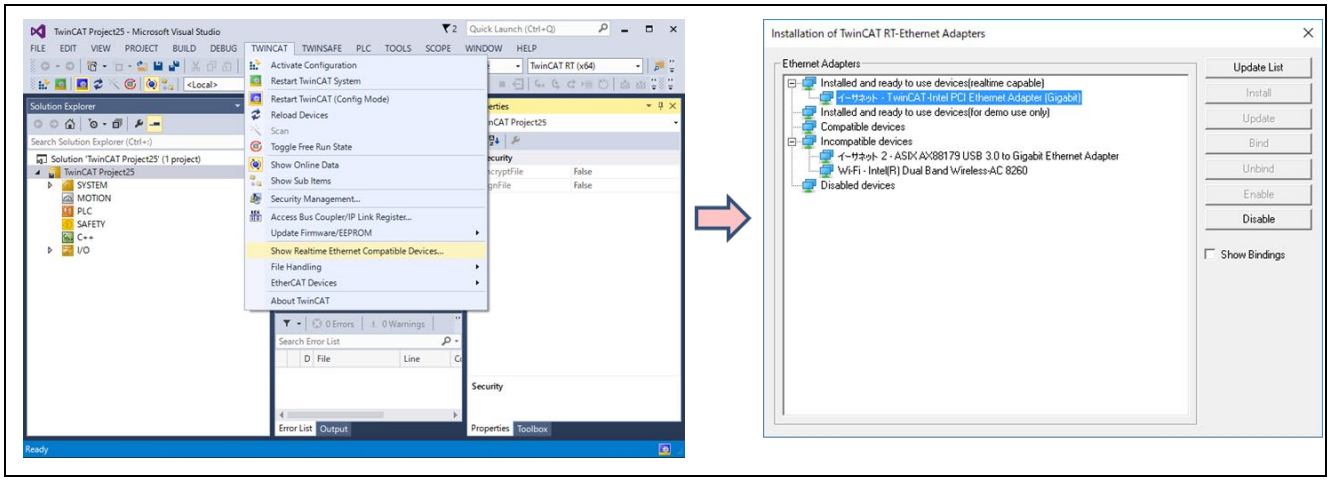
ESI file for current release available at,

"common\ecat_IO\ESI\Renesas EtherCAT RZN2.xml"

4.2 Add Driver

Add the Ether driver for TwinCAT. (First time only)
From the start menu, select [TwinCAT3] → [Show Realtime Ethernet Compatible Devise].

Select the connected Ether port from the communication ports and install it.



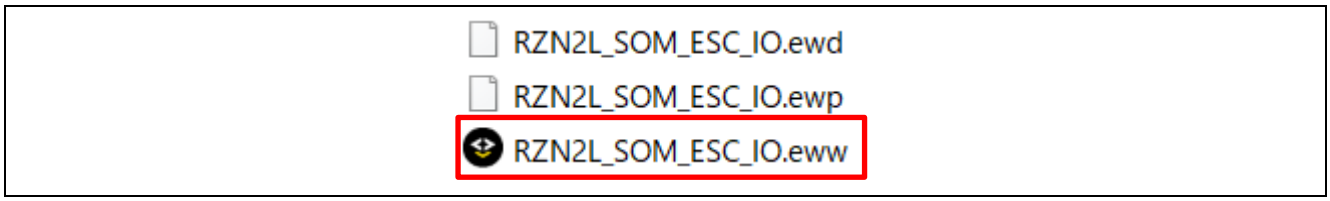
5. Running the sample application

5.1 Build and debug sample code for EWARM

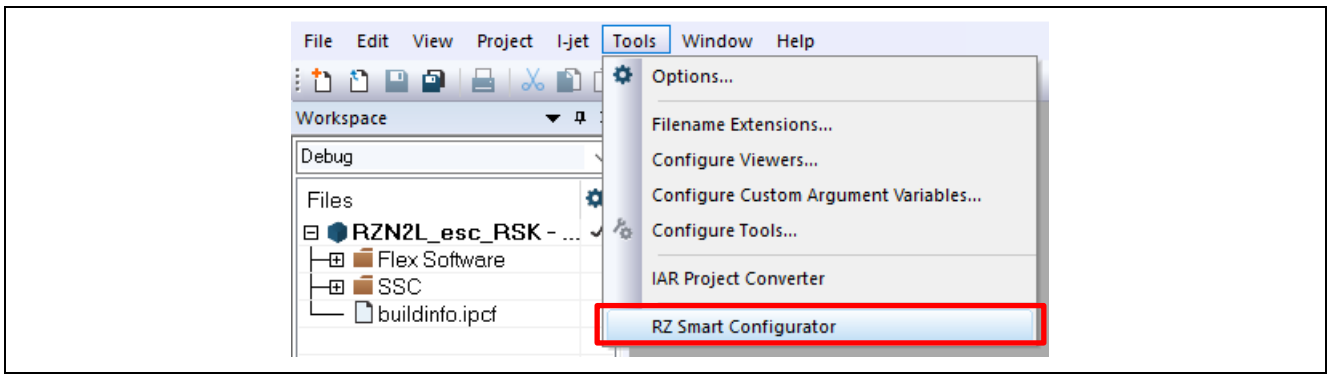
Build the sample code and load it into RAM using IAR Embedded Workbench.

Note). Please install FSP Smart Configurator in advance.
Refer to the latest getting started guide.(R01an6434ejxxxx- rzt2-rzn2.pdf)
Replace the project name in the figure with the project name of this sample project.

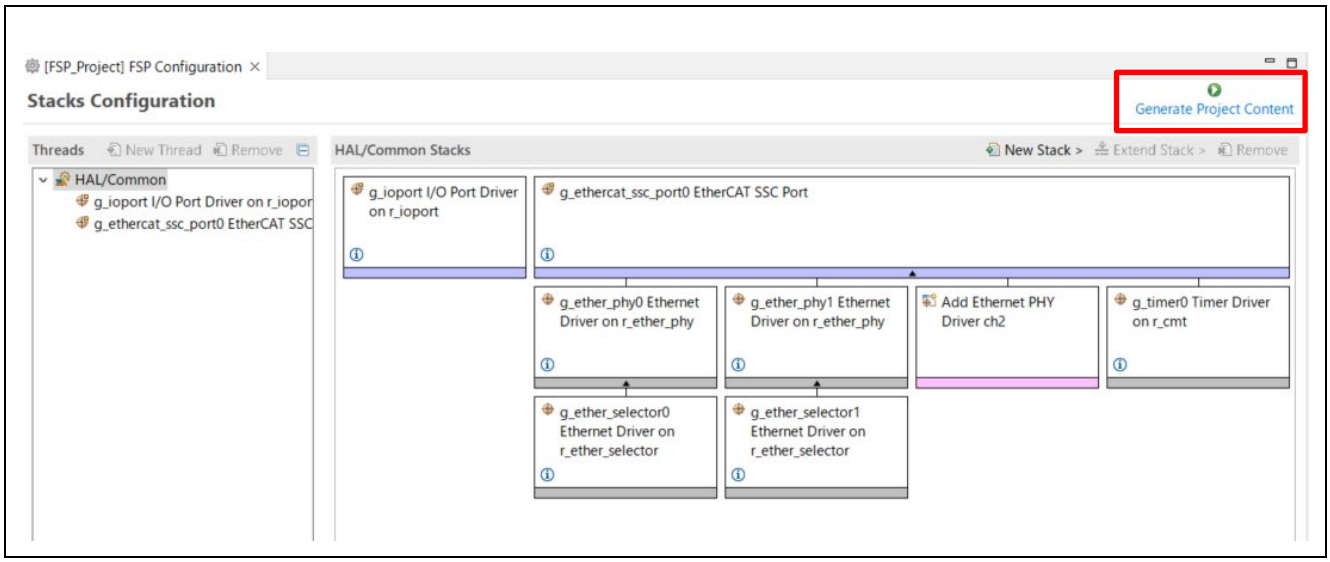
1. Open the sample project. **“project\rzn2l_som\ecat_IO\ewarm\RZN2L_SOM_ESC_IO.eww”**



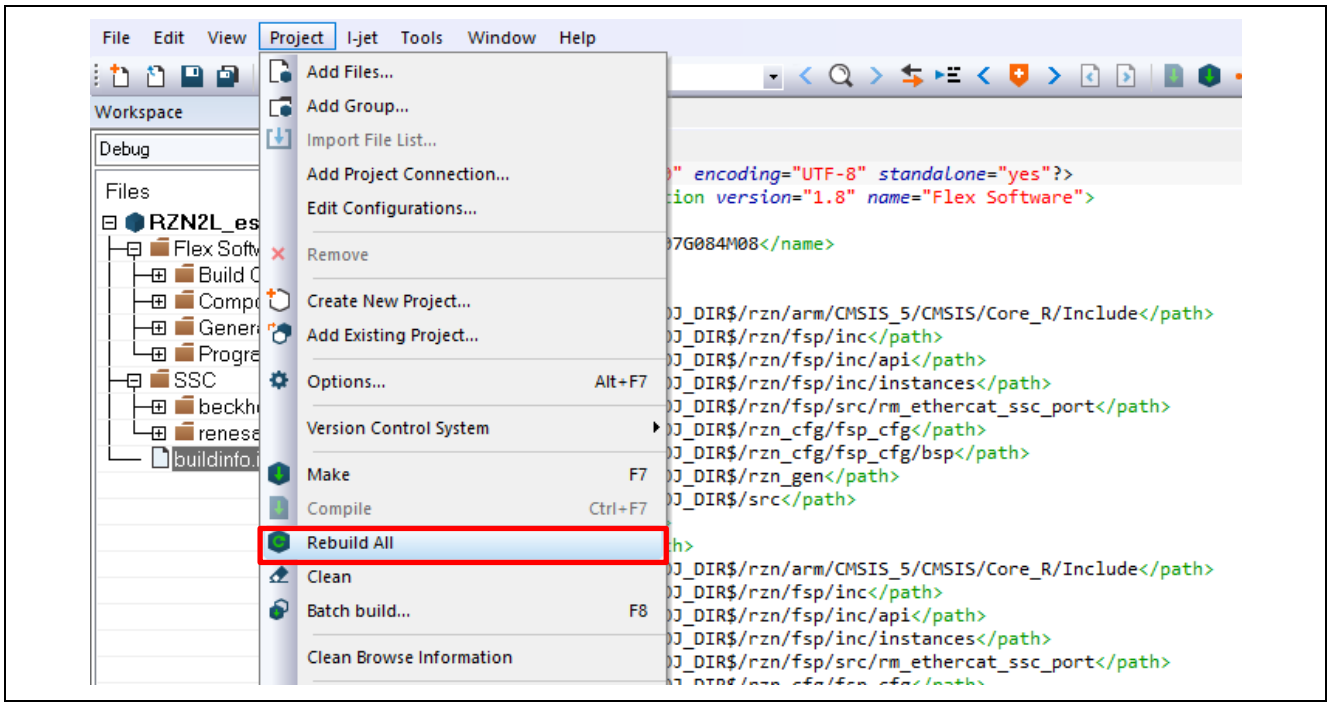
2. Open the “RZ Smart Configurator”



3. Generate the code with "Generate Project Content".

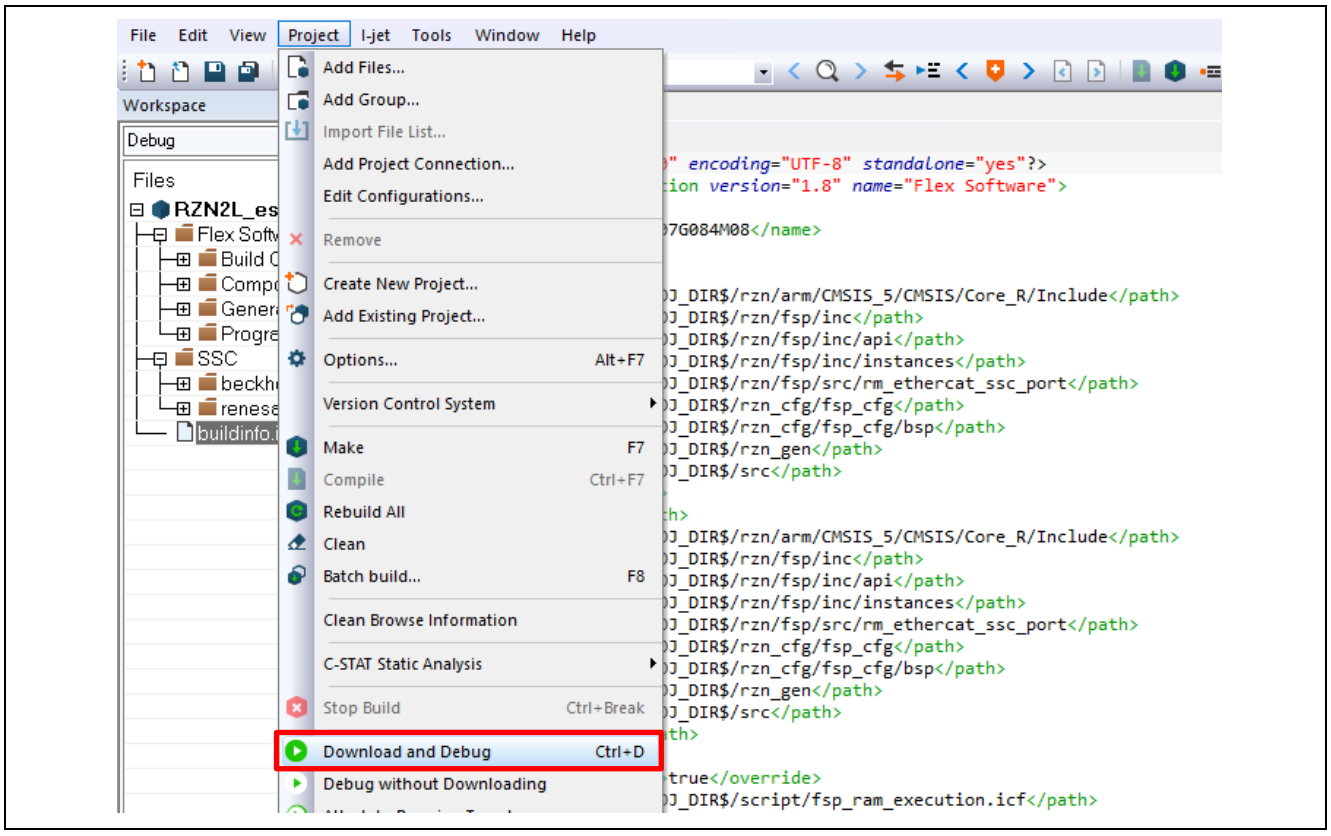


4. Select the “Rebuild All” item from the “Project” menu to rebuild the project.

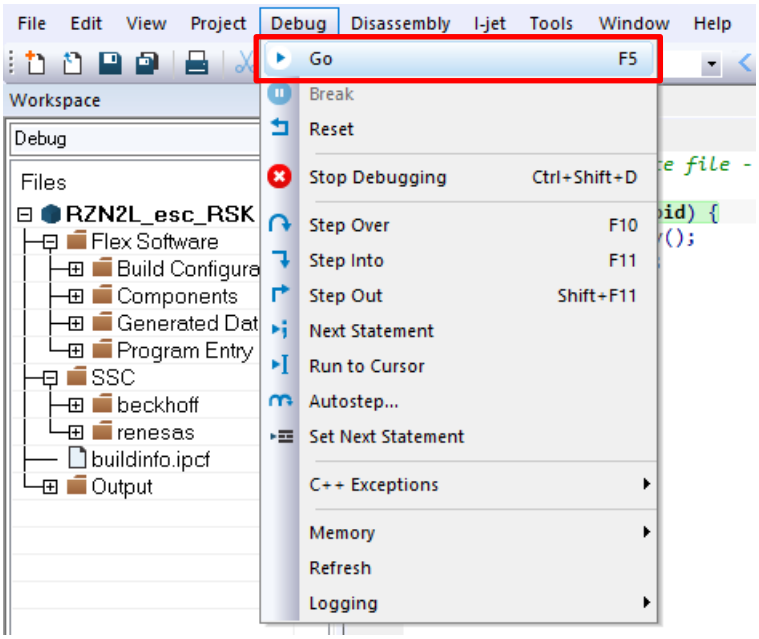


5. Press the “RESET” switch of the RZ/N2L Industrial Network SOM Kit.

6. While the board and I-jet are connected, click on the “Download and debug” button in the “Project” toolbar.



7. Press the "Resume" button for the project. Program is running.



5.2 Setting sample code for GCC

5.2.1 Erasing the flash memory

First, erase the flash memory by following the steps below. This step can be skipped after erasing the flash memory.

Open the J-Link Commander.

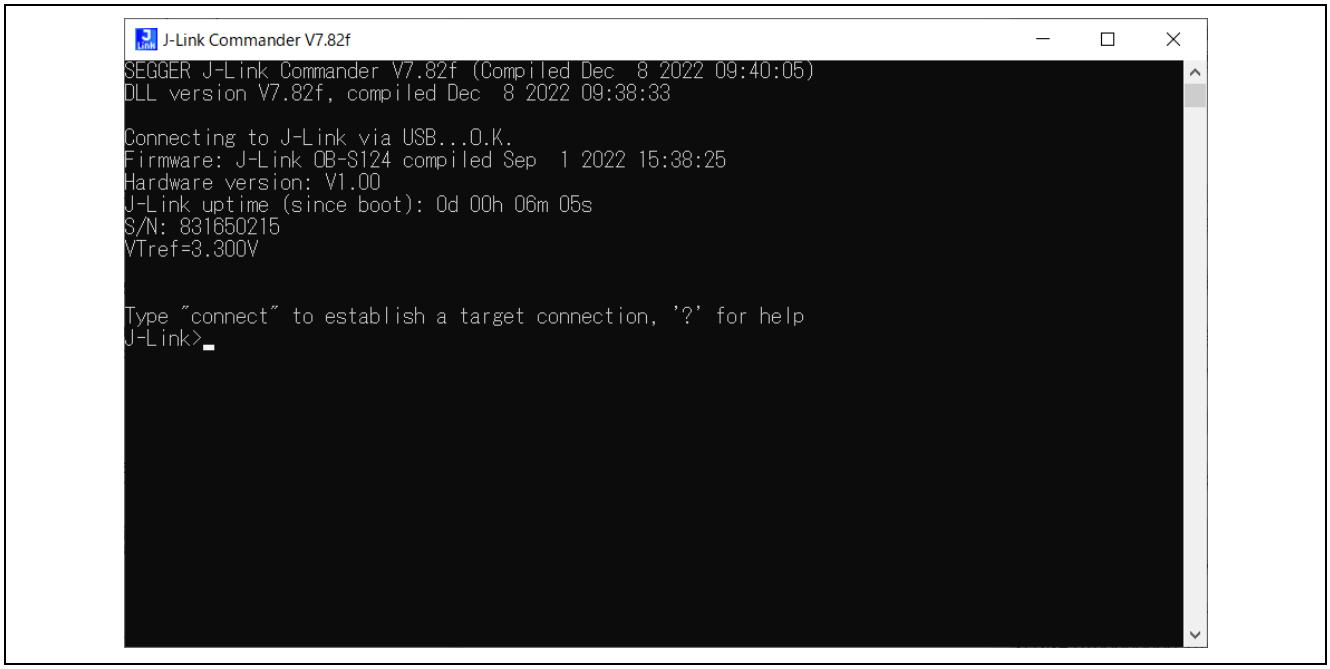


Figure 5-1 Open J-Link Commander

First, type “connect” to establish a target connection and press enter.

Next, specify the connection conditions as follows.

- Device> (Default = press enter)
- TIF>S
- Speed> (Default = press enter)

After that, confirm the message “Cortex-R52 identified.” Is displayed.

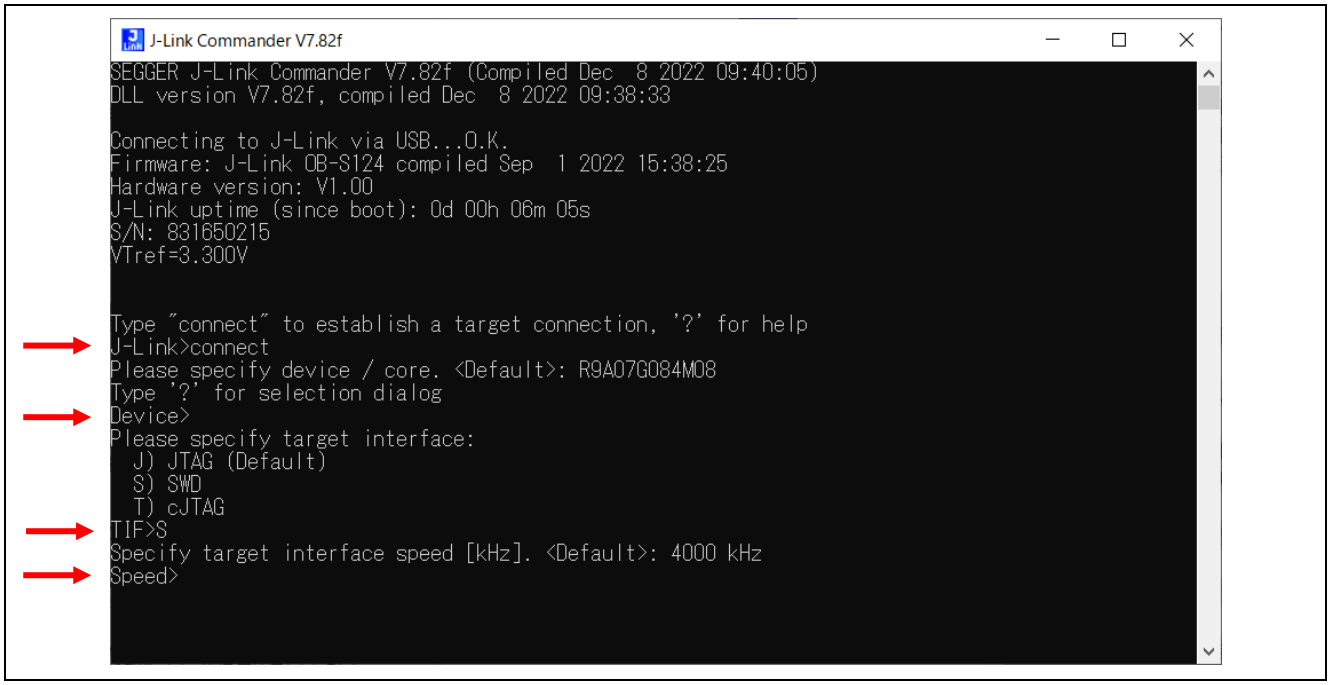


Figure 5-2 Connection conditions (1/2)

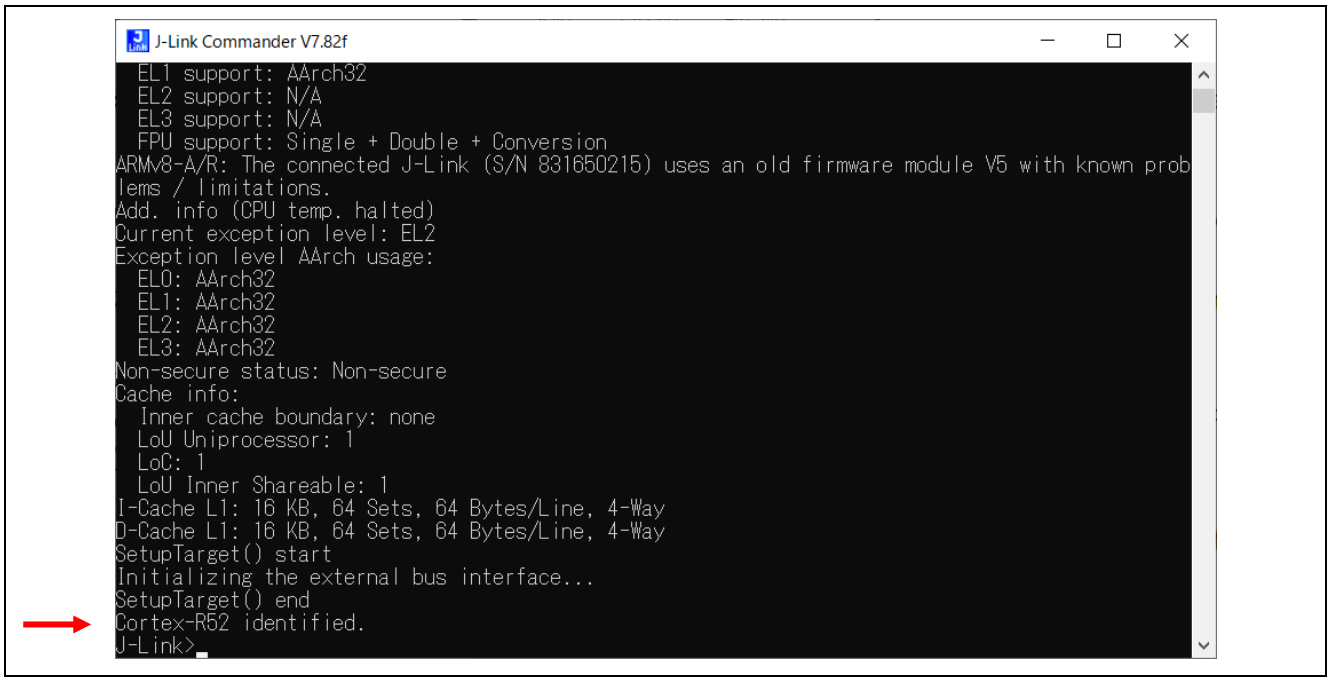


Figure 5-3 Connection conditions (2/2)

Use the commands below to enable flash erase and erase the flash memory.

- >exec EnableEraseAllFlashBanks
- >Erase 0x60000000, 0x60100000

After that, confirm the message “Erasing done.” Is displayed.

Enter “q” to exit J-Link Commander.

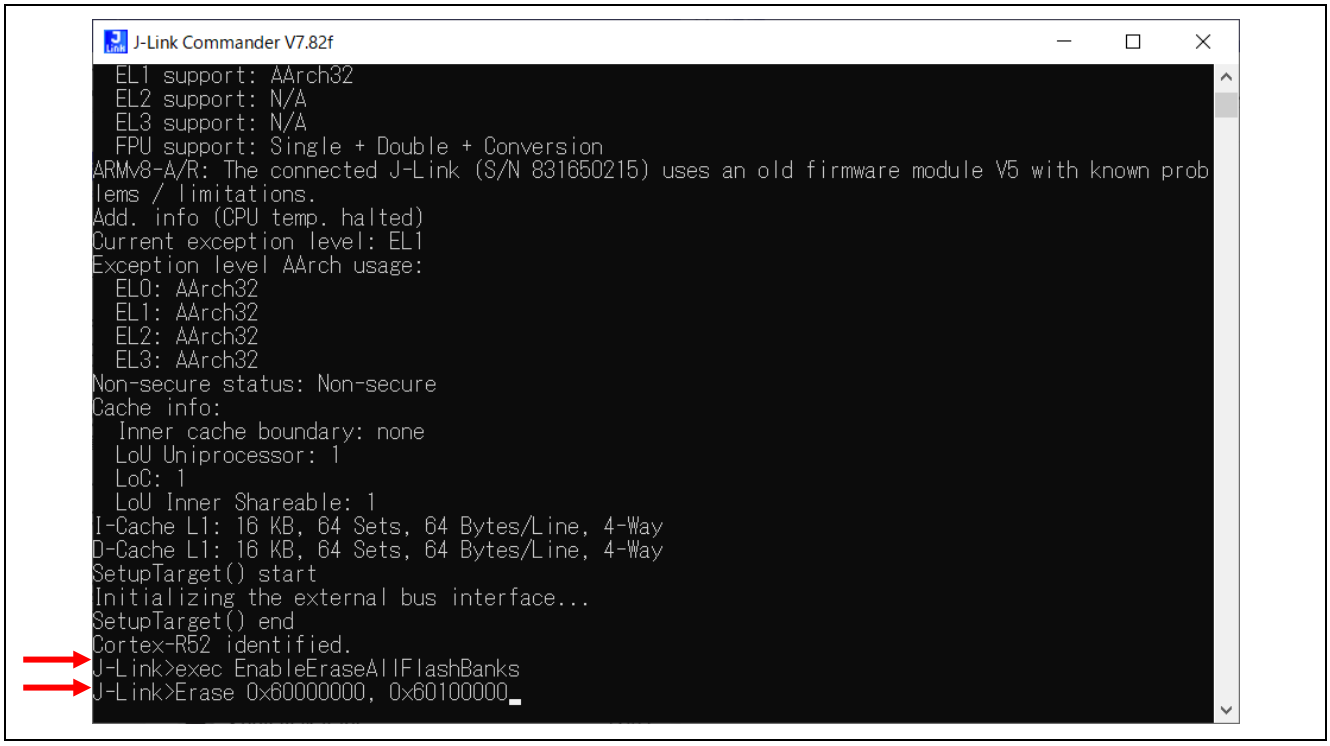


Figure 5-4 Erase flash memory (1/2)

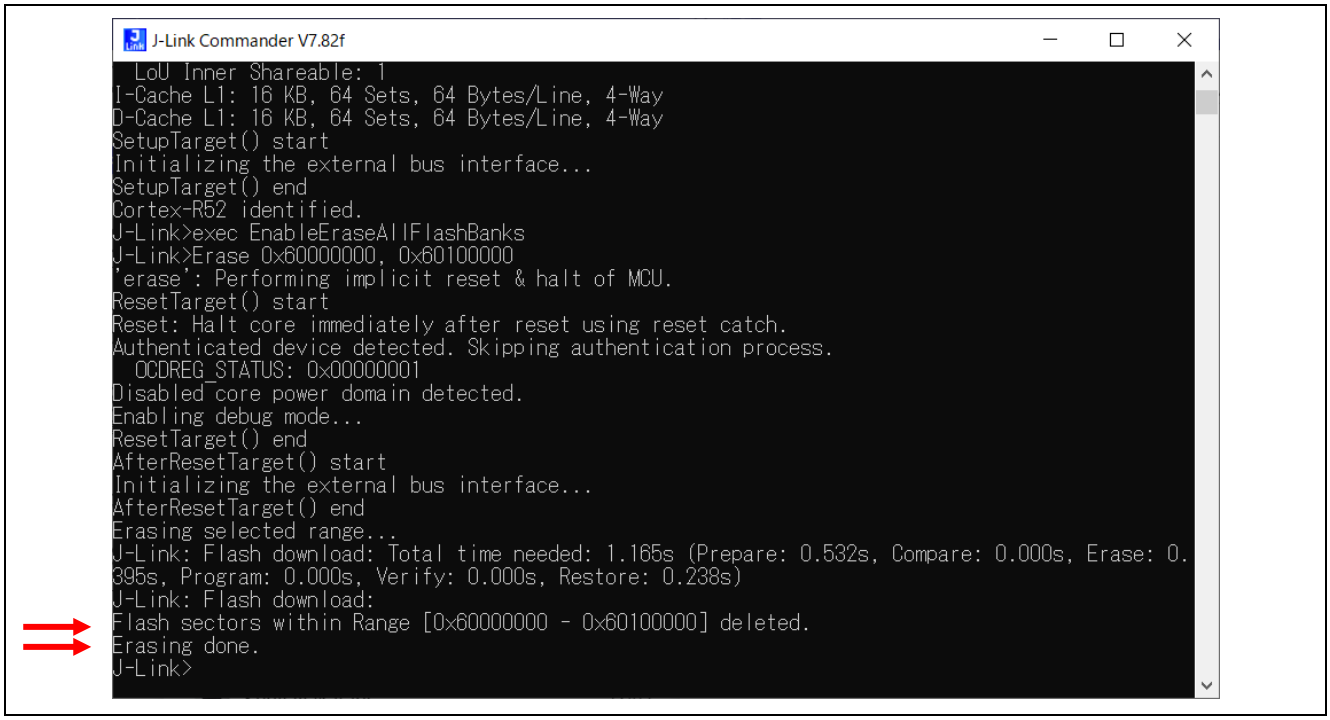


Figure 5-5 Erase flash memory (2/2)

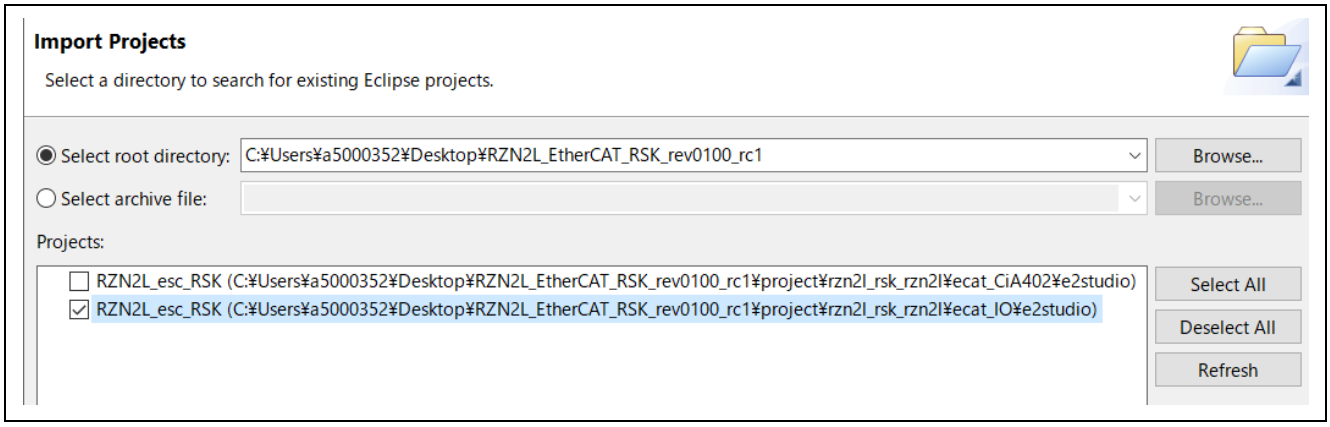
5.2.2 Setting sample code for GCC

Build the sample code and load it into RAM using Renesas Electronics e² studio.

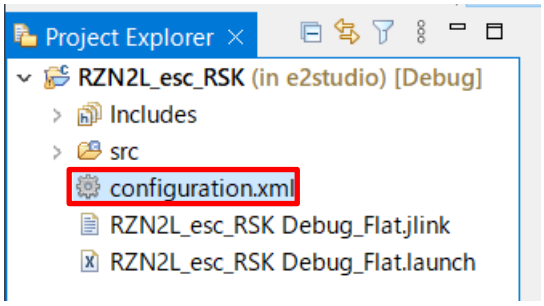
Note). Please install e2studio and adapt the FSP_Packs_v1.0.0 in advance.
Refer to the latest getting started guide.(R01an6434ejxxxx- rzt2-rzn2.pdf)

Replace the project name in the figure with the project name of this sample project.

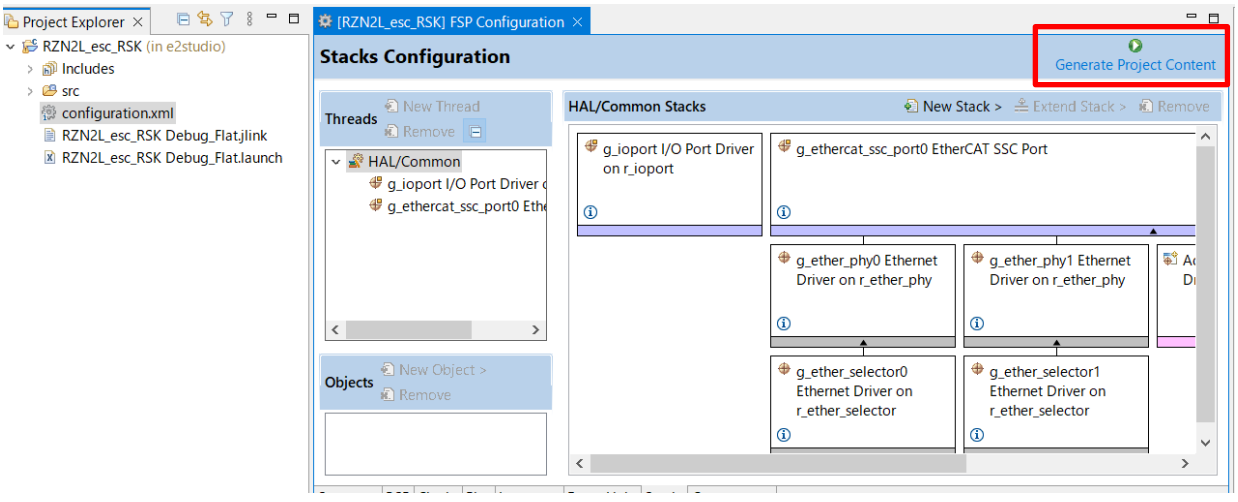
1. Import the sample project. After the program is started, by selecting [File] → [Import] → [Existing Projects into Workspace]. Check the "select root directory" and select “project\rzn2l_som\ecat_IO\e2studio” folder →[Finish].



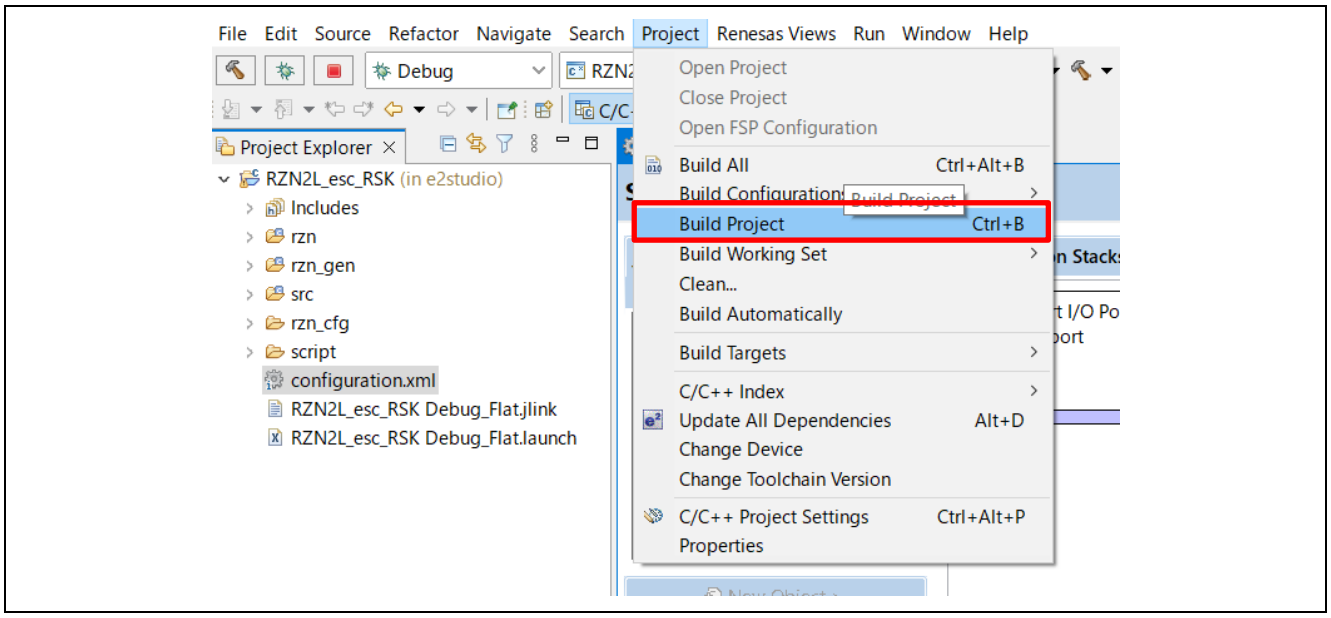
2. Open "cofiguration.xml" in the "RZN2L_SOM_ESC_IO " project



3. Generate the code with "Generate Project Content".

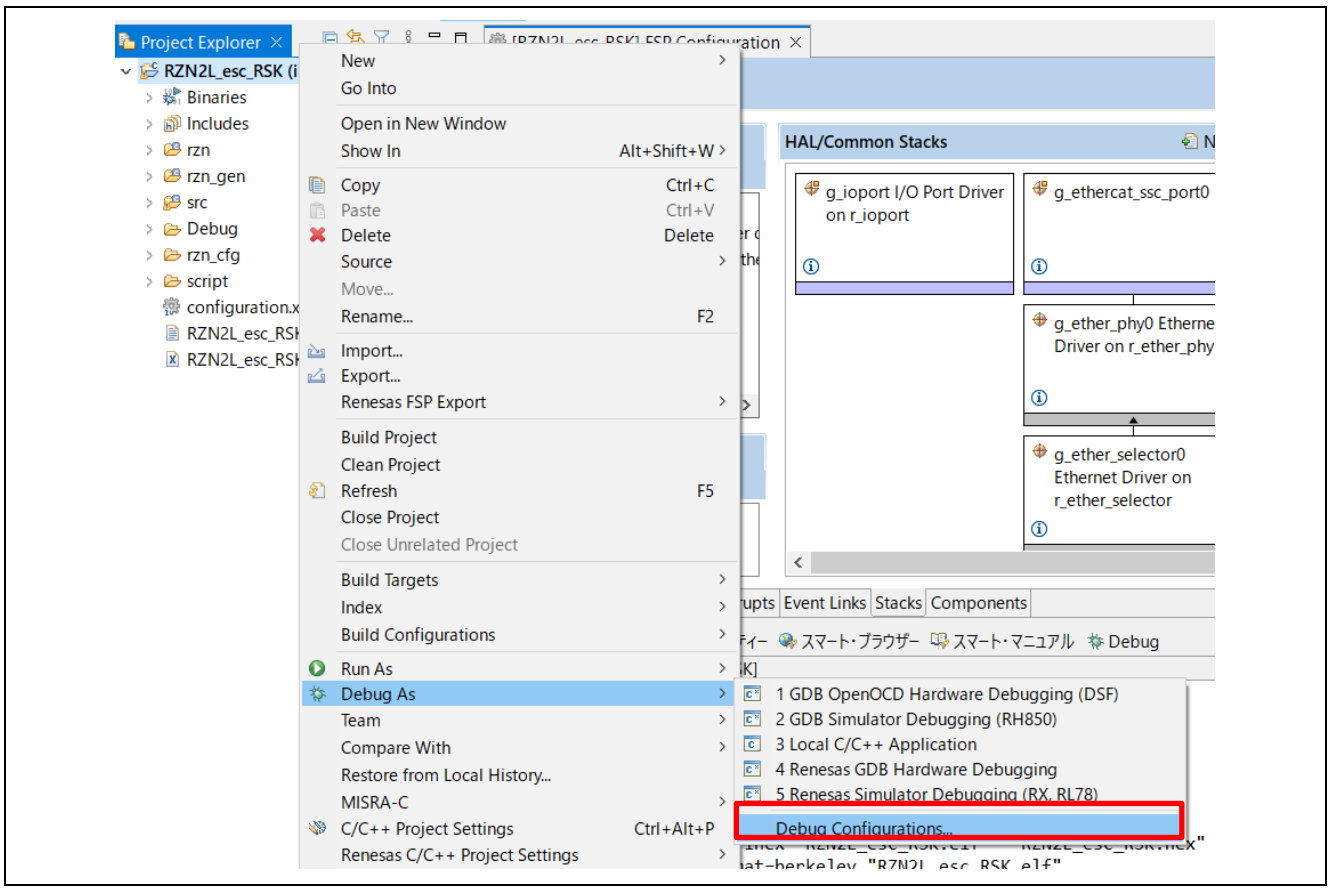


4. Select and build the "RZN2L_SOM_ESC_IO" project.

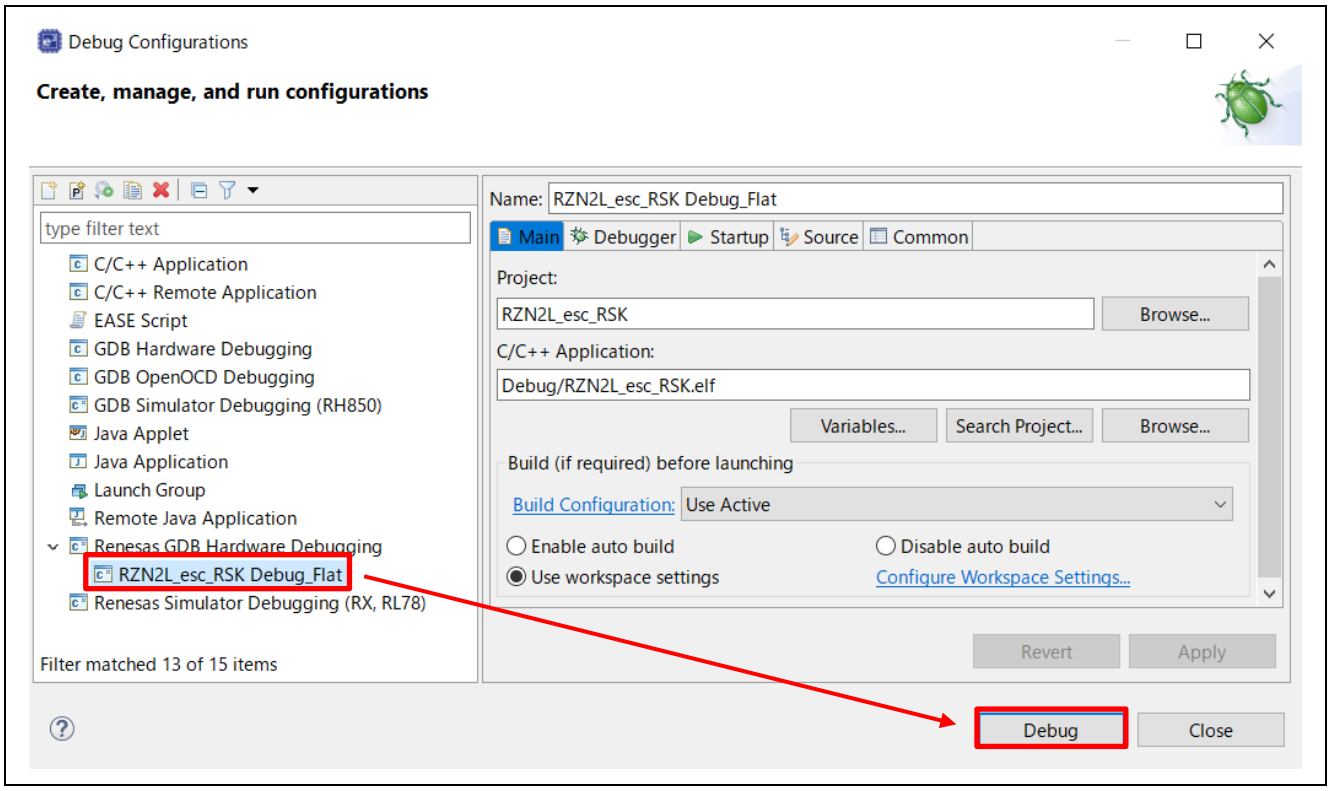


5. Press the “RESET” switch of the RZ/N2L Industrial Network SOM Kit.

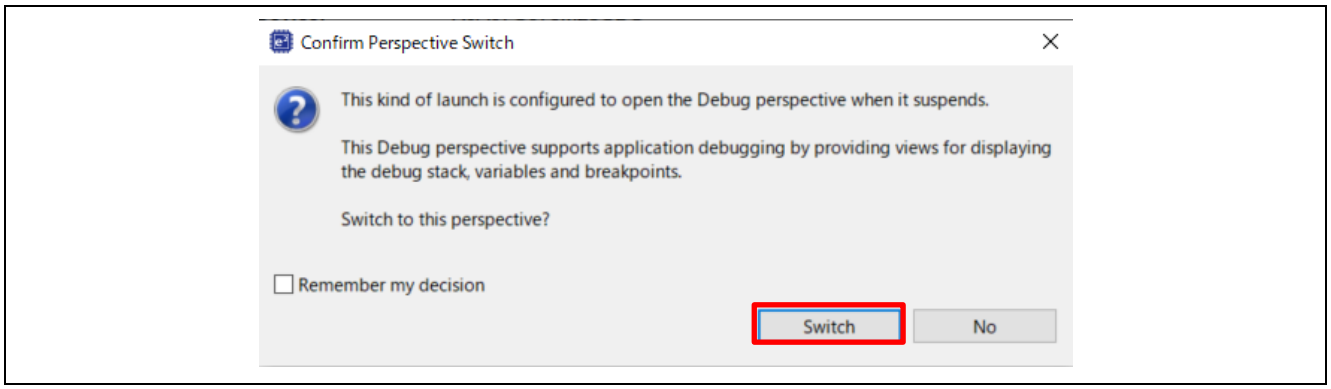
6. Connect J-Link to the SOM Kit, start debugging in the following procedure.
In [Project Explorer] view, right click the node of project to be debugged and select [Debug As] → [Debug Configurations].



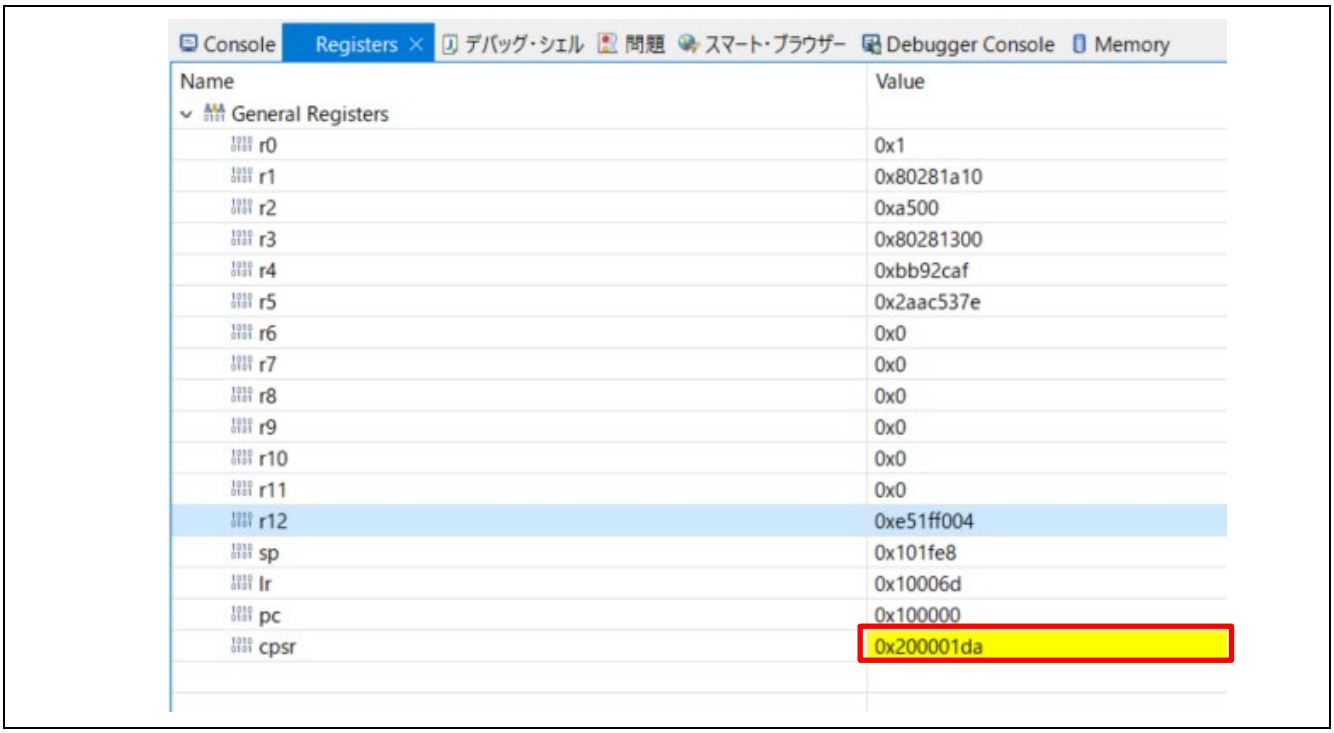
[Renesas DBG Hardware Debugging] → [RZN2L_SOM_ESC_IO Debug_Flat] item, then press [Debug]



Following dialog will appear, so switch to the debug screen.



7. Before running the loaded program, change the CPSR register of CR52 general register on Registers tabs.
   Change the register value from “0x200001fa” to “0x200001da”.
   If the CPSR register value has not changed, program will stop at Default_Handler () at run time.



8. Press the "Resume" button for the project. Program will stop at hal_entry ().
   Press the "Resume" button again. Program is running.

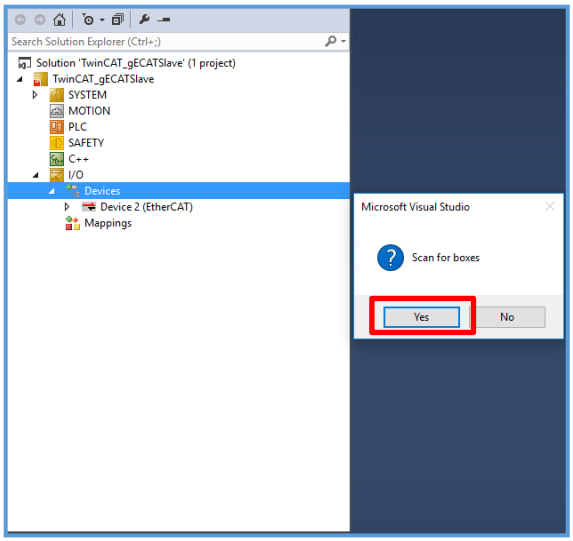
6. Connecting to TwinCAT3

Start TwinCAT3 by using the procedure described below,
From the start menu, select [Beckhoff] → [TwinCAT3] → [TwinCAT XAE].

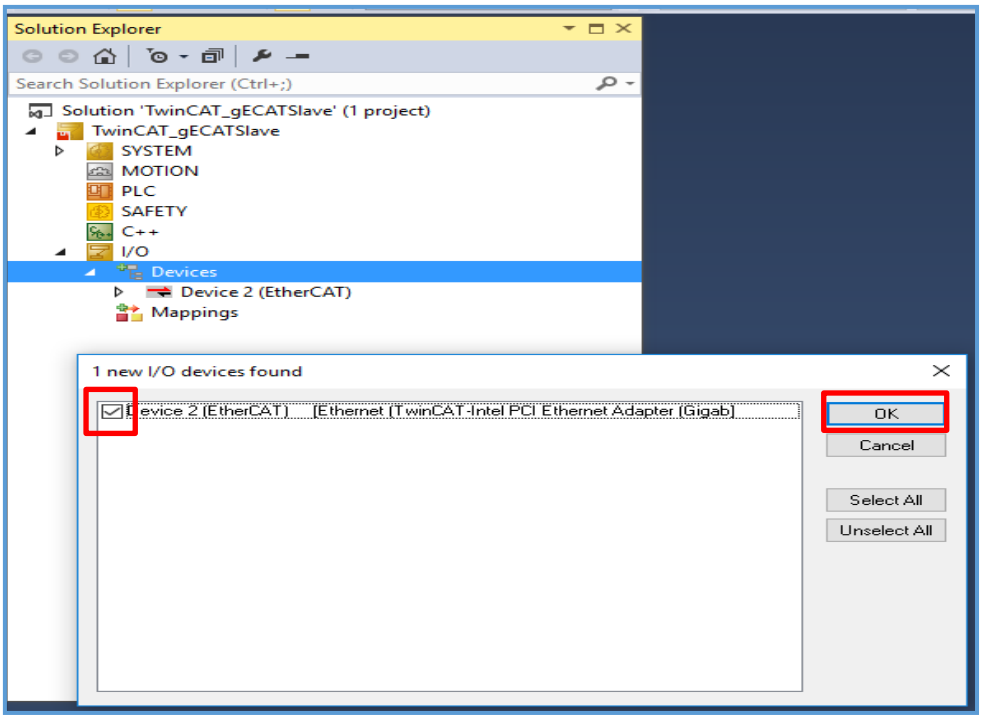
After the program is started, by selecting [File] → [New] → [Project], create a new project of the TwinCAT XAE Project type. The subsequent procedure is described below.

6.1 Scanning I/O Devices

1. (Scan for devices): Under solution explorer -> I/O -> Devices, select ‘Scan’ as in Figure below

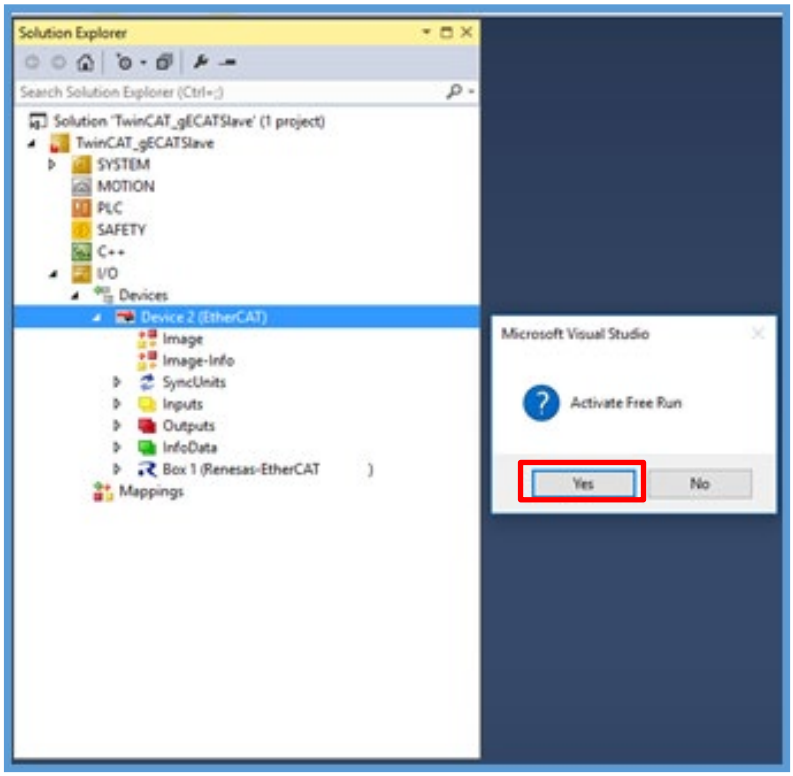


2. (Selecting port): The EtherCAT port will be displayed as below. Select and press OK.



Note). This will list EtherCAT master if a valid slave is present in the network.

3. (Activate slave): The slave is listed in the boxes, in our case “Renesas EtherCAT” in box1 shown in figure below. Press activate free run.



6.2 Updating EEPROM Data

If the data of another application has already been written to the EEPROM, replace the data.
The following shows the procedure for replacing the data on the EEPROM:

1. Double-click [Box 1] to display a panel on the right side of the window.
2. Select the [EtherCAT] tab.
3. Click the [Advanced Setting] button.
4. Select [ESC Access] → [EEPROM] → [Hex Editor].
5. Select [Download from List] → Select ESI File
   "*common\ecat_IO\ESI\esi\Renesas EtherCAT RZN2.xml*"
6. Select "Renesas EtherCAT RZ/N2 2port"
7. OK and Download.

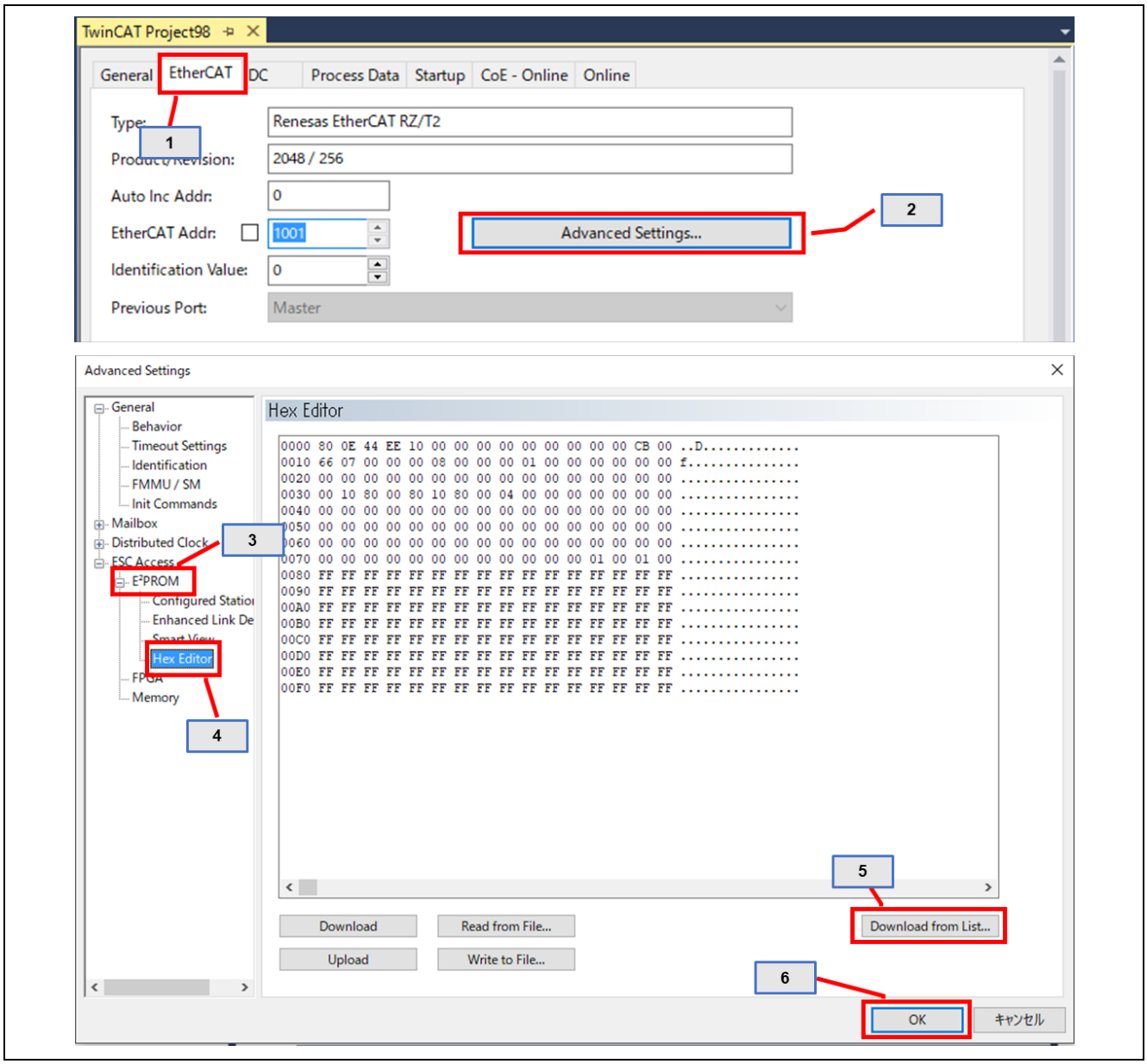


Figure 6.1: EEPROM update

Option A - Create ESI binary file from ESI XML and download.

1. SSC Tool → [Tool] → [EEPROM Programmer].
2. [FILE] → [OPEN] →Browse and select the ESI file.
3. [FILE] → [Save AS] → Select type as binary.
4. A binary file will be generated in the specified folder.
5. [Read from File] Select the ESI binary file → [Download].
6. Confirm the write status using [Upload] option.

After the data is replaced, restart the RZ/N2L (by turning it off and on, or resetting it) so that the new data is applied to the microcomputer. Execute [Restart TwinCAT System].

6.3 Sync Modes

The Slave Stack Code supports different modes of synchronization which are based on three physical signals: (PDI_) IRQ, Sync0 and Sync1.
After setting the synchronous mode, please reflect the setting in [TwinCAT] → [Restart TwinCAT (Config Mode)] → [Reload Devices].

6.3.1 Free Run

In this mode there is no slave application synchronization, AL_EVENT_ENABLED and DC_SUPPORTED disabled.

6.3.2 Sync Manager Synchronization

In this mode the slave application is executed as Sync Manager synchronous. AL_EVENT_ENABLED enabled and DC_SUPPORTED disabled.

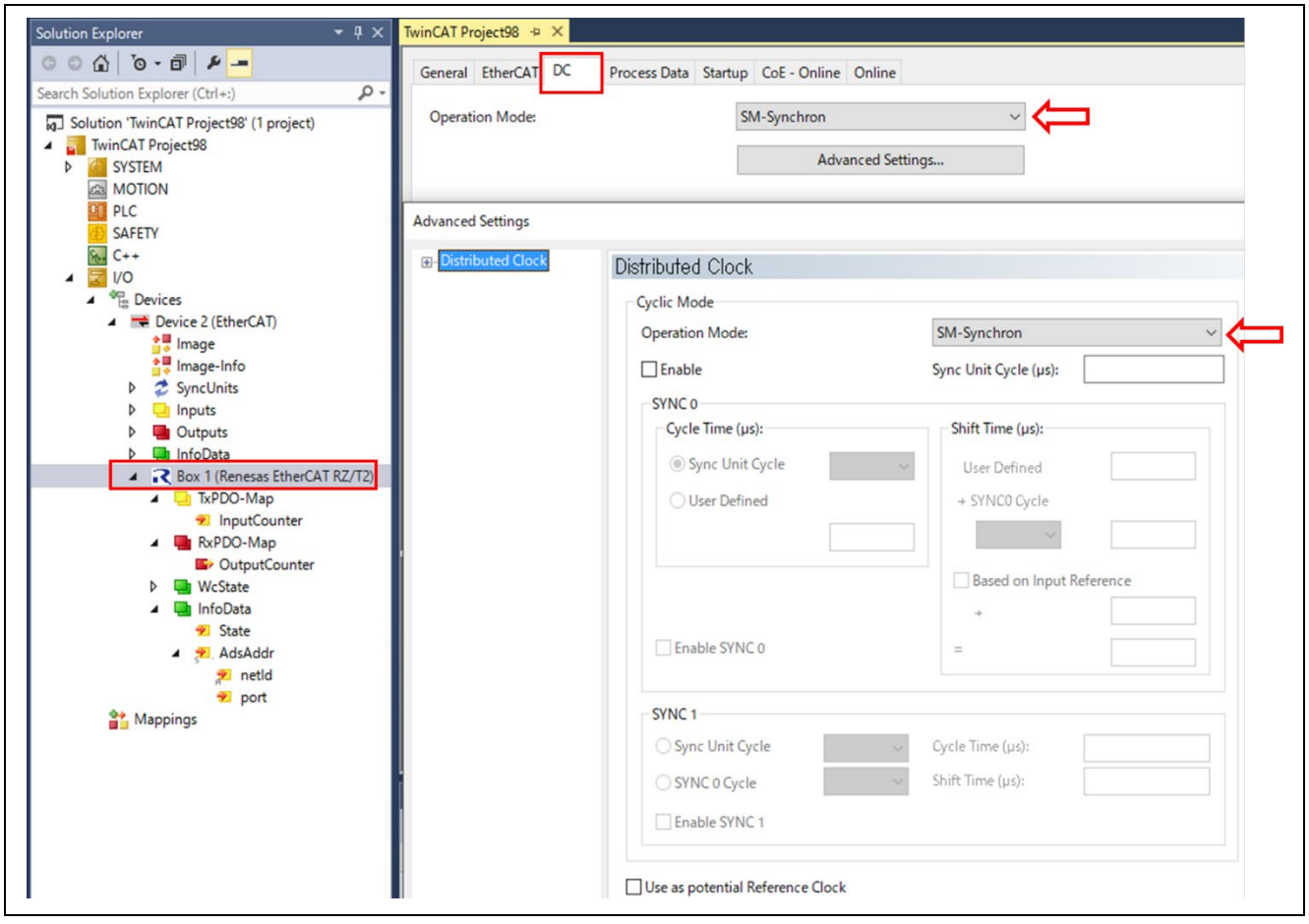


Figure 6.2: SM- Synchronization

6.3.3 DC Synchronization

SyncManager/Sync0 & SyncManager/Sync0/Sync1 synchronous, both AL_EVENT_ENABLED and DC_SUPPORTED are enabled.

1. Master setting for enabling DC synchronization.

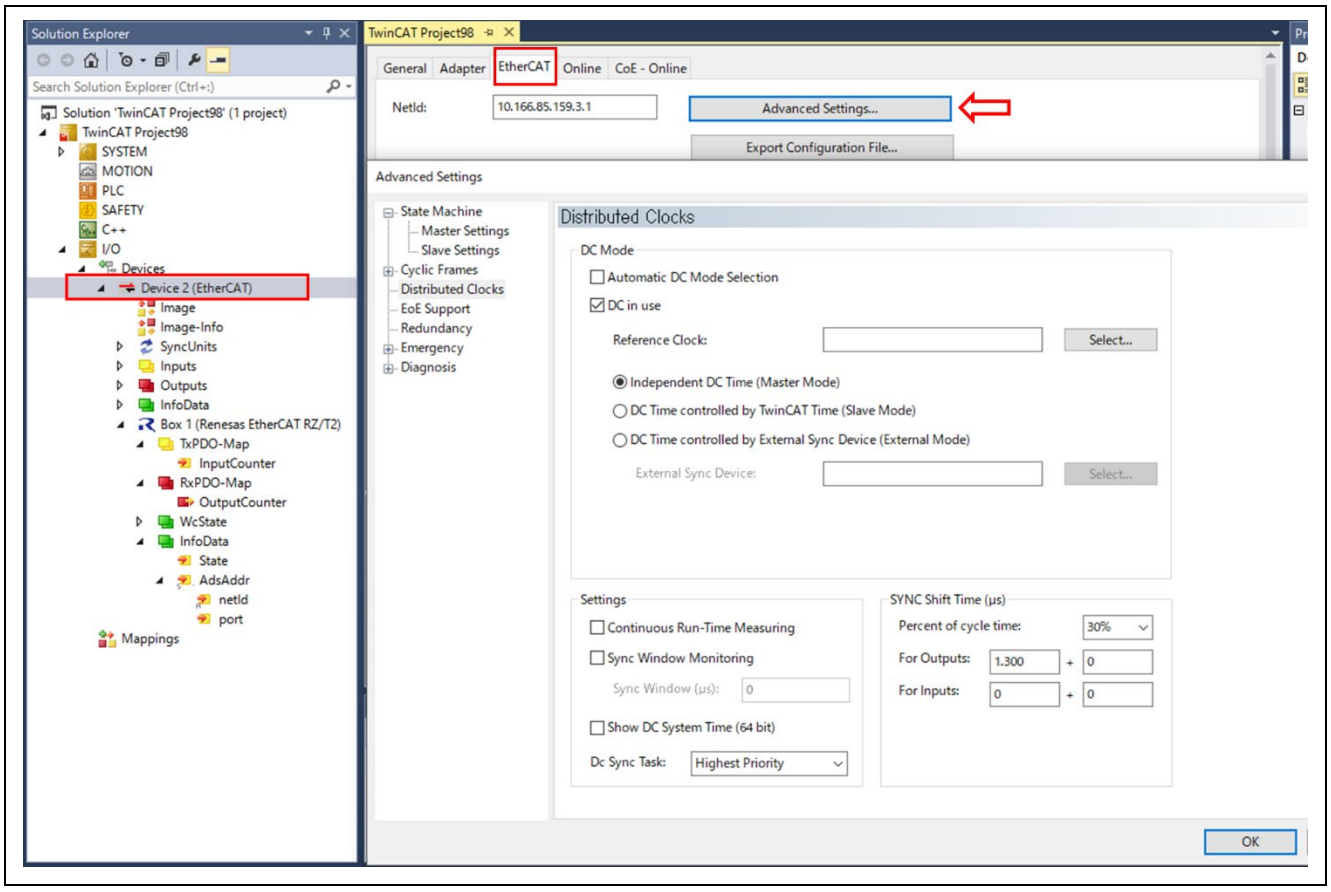


Figure 6.3: DC Setting-Master

2. Slave setting for enabling DC synchronization.

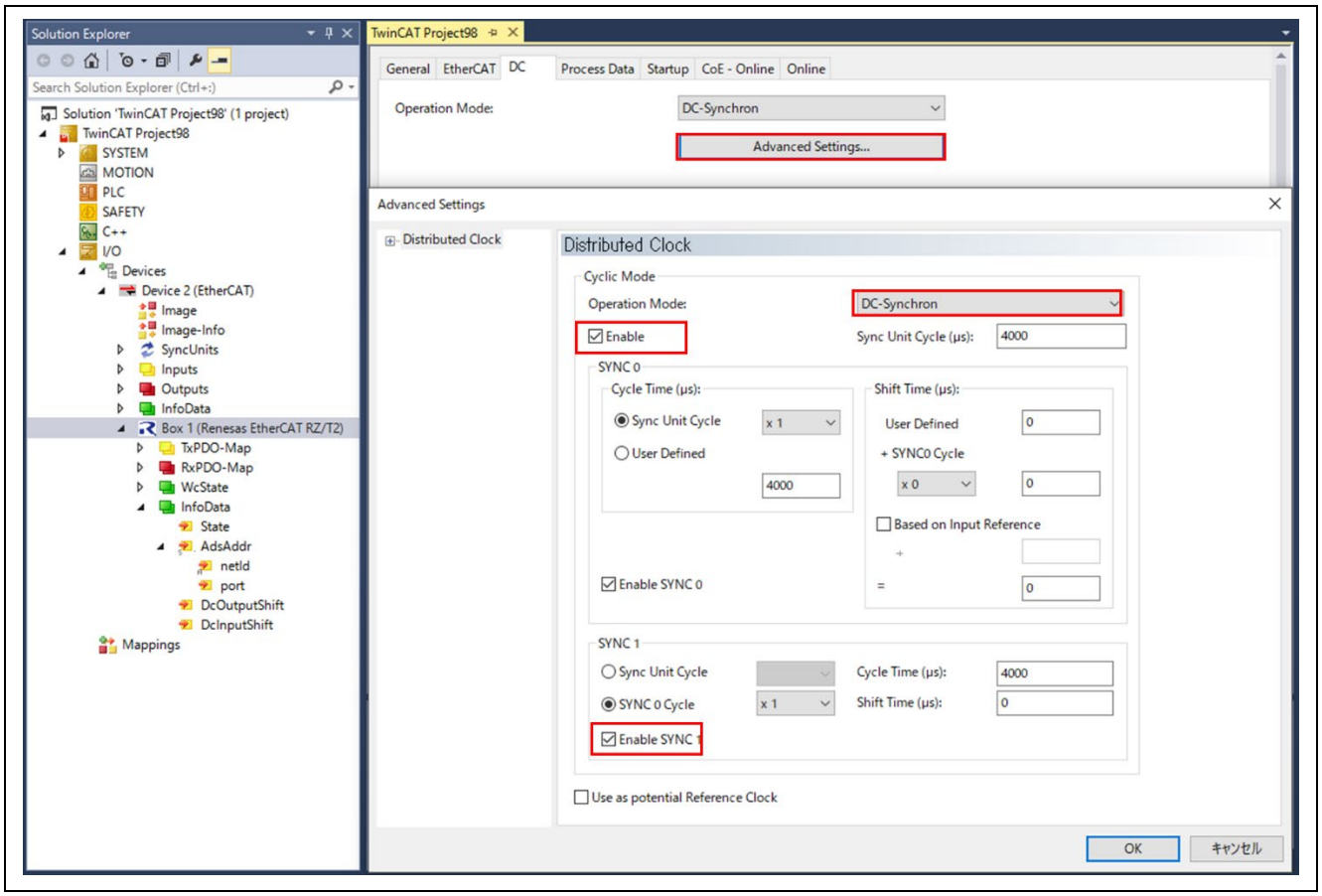


Figure 6.4: DC Setting Slave

Note: SYNC0 and SYNC1 are level triggered interrupt. It can cause synchronization issues due to multiple interrupts in a single pulse. To avoid this issue, pulse width can be reduced by changing the word 2 of EEPROM configuration value in ESI file. It sets the register 0x982 register of EtherCAT slave during power up. Also can be solved by waiting for the line to be low in the interrupt handler by reading the status register 0x98E.

6.4 Testing the I/O Controller

I/O communication can be confirmed by the LED and the Dip Switch of the SOM Kit..

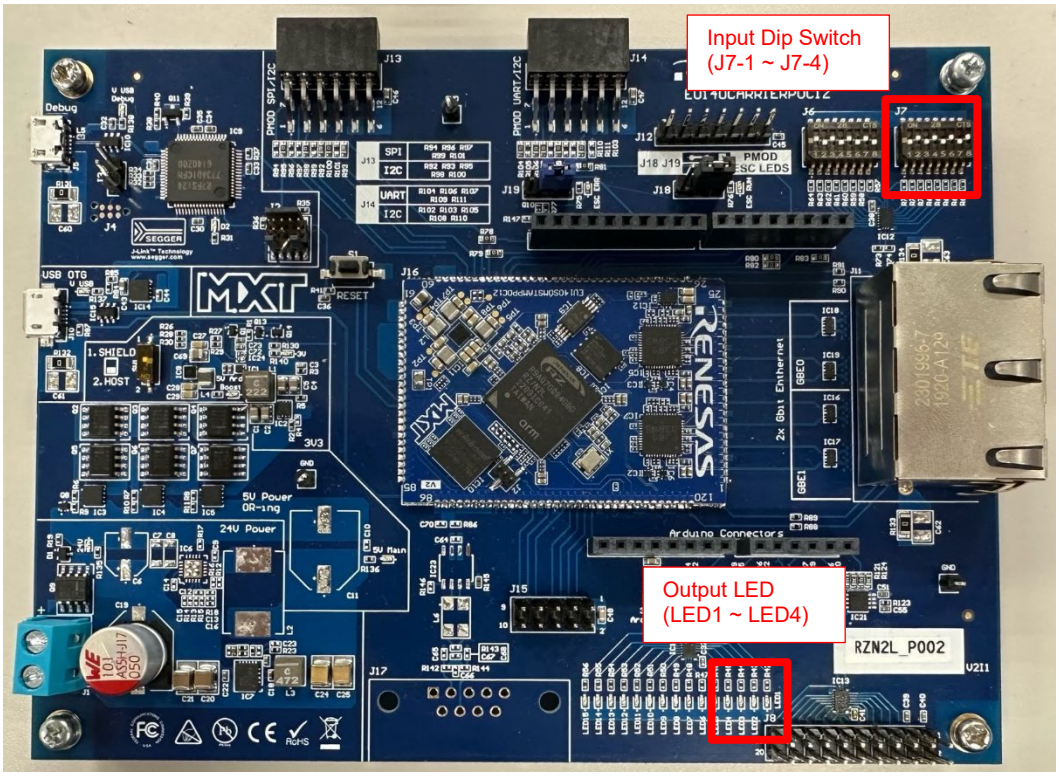


Figure 6.5: LED and DIP SW

To confirm the I/O output, use TwinCAT3 to select [Output Counter] → [Online] →[Write] and enter the desired value.
LED1 to LED4 glow up according to the set value.

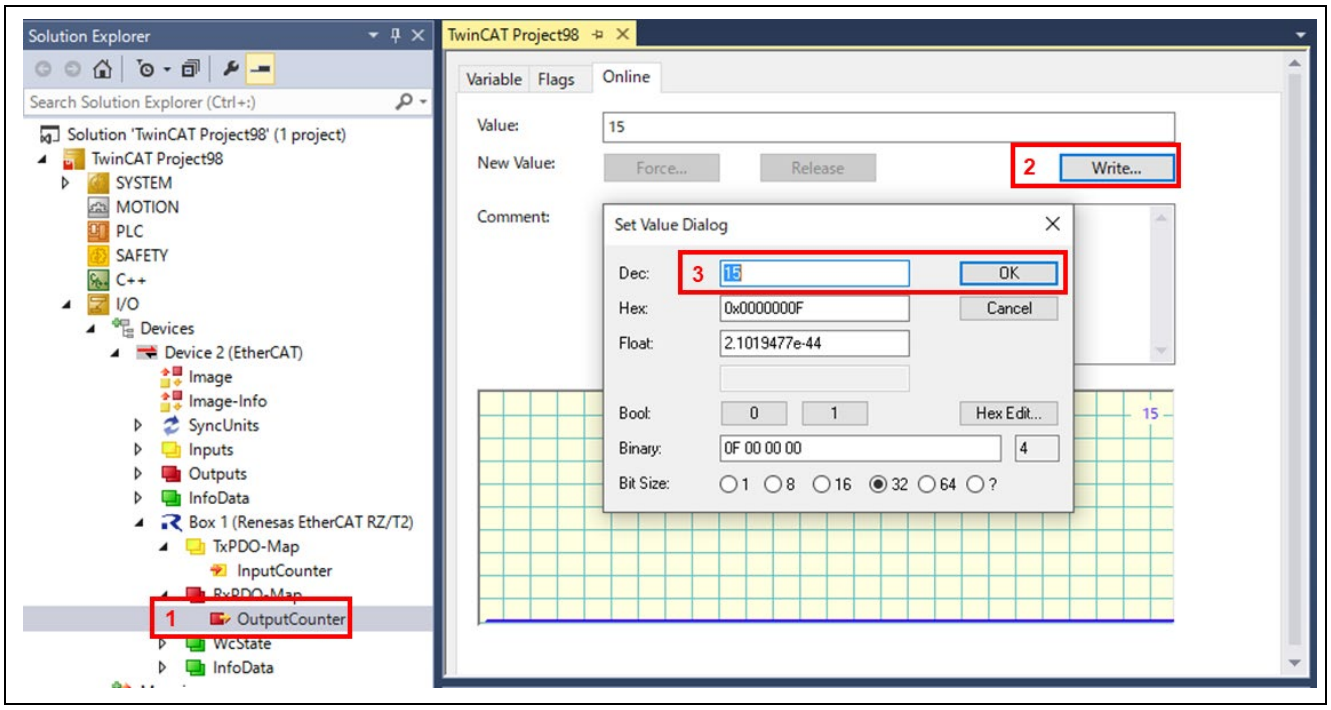


Figure 6.6: I/O Output setting

To confirm the I/O input, use TwinCAT3 to select [Input Counter] → [Online] , 4-bit input value of Dip Switch (J7-1 to J7-4) is displayed in Value.

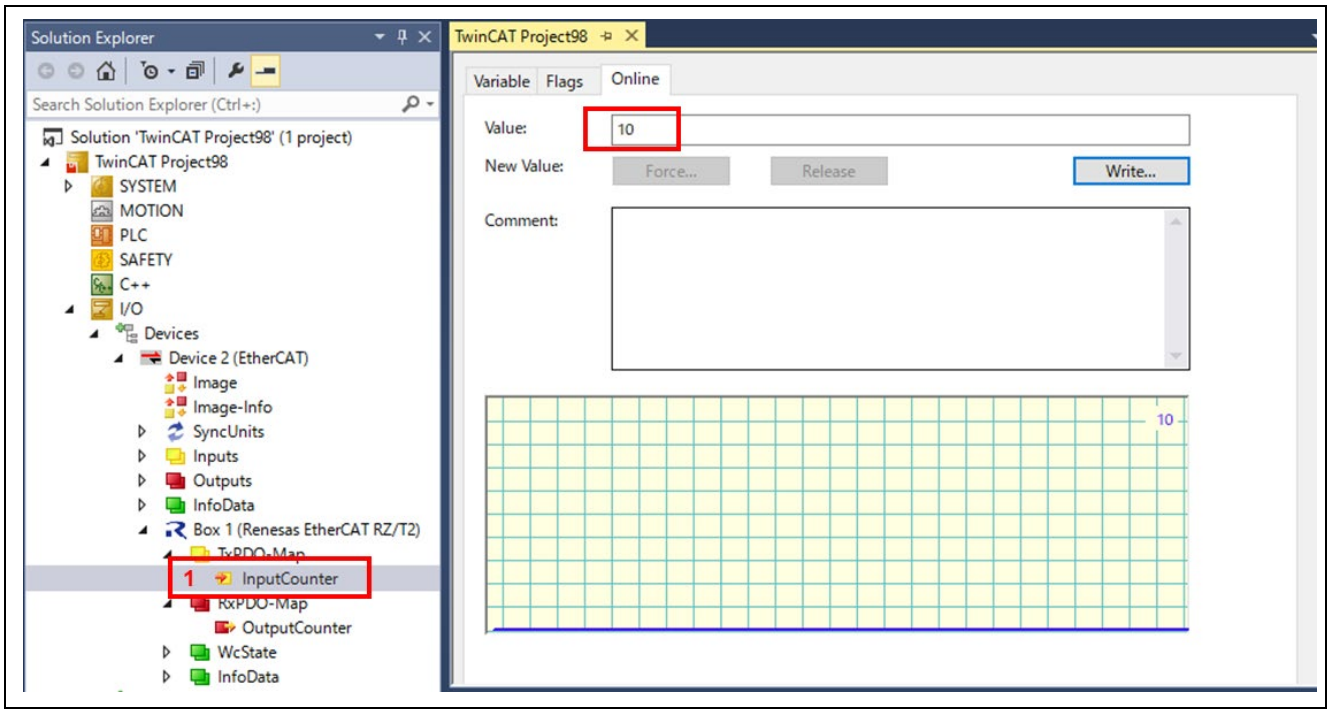


Figure 6.7: I/O Input setting

7. Appendix: FSP Configuration for VSC8531 and SSC port

RZ/N2L Industrial Network SOM Kit has VSC8531 as PHY chip.
If reconfiguring by latest FSP, FSP configuration and source code needs to change from default.

In addition, since interrupts are used for IO control, SSC port driver also needs to change.

(1) Regenerate source files by lates FSP

Remove the following four folders. After that, open the project according to section 5.

- When using e2studio, \project\rzn2l_som\ecat_IO\e2studio
- When using EWARM, \project\rzn2l_som\ecat_IO\ewarm

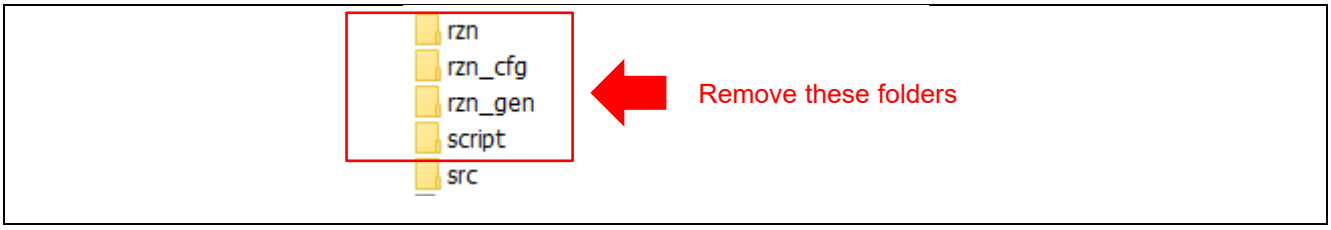


Figure 7-1 Remove folder generated by FSP

(2) Change ethernet driver configuration for VSC8531

Configure g_ether_phy0 Ethernet Driver on r_ether_phy for VSC8531 as shown in Figure 7-2.
Configuration value for VSC8531 shows in Table 7-1.

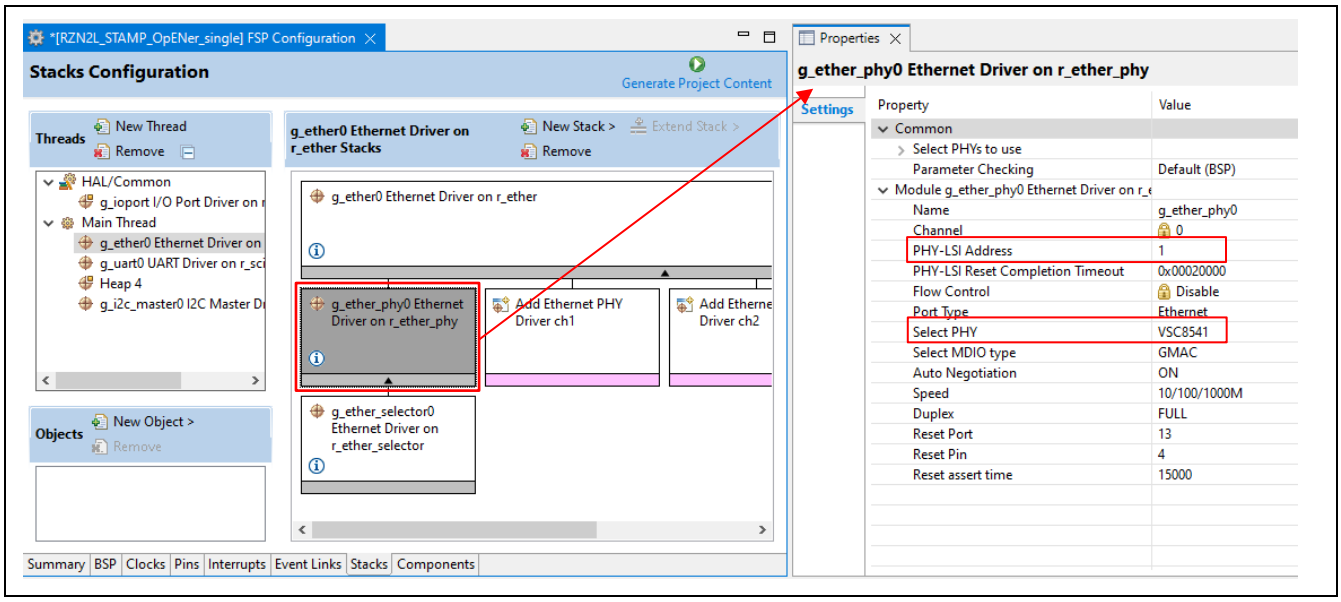


Figure 7-2 Ethernet Driver Configuration for VSC8531 (e.g. ETH0)

Table 7-1 FSP Configuration Value for VSC8531

Items	Default value	Config value for VSC8531	
		ETH0	ETH1
PHY-LSI Address	0	0	1
Select PHY	Default	VSC8541	VSC8541

(3) Add initialization code for VSC8531

The following code for VSC8531 initialization should be added to “ether_phy_targets_initialize_vsc8541” function in rzn/fsp/src/r_ether_phy/r_ether_phy.c.

The inclusion of “board_som.h” is aiso required for code activation.

```
#include "board_som.h"
                                        ~~ Omission ~~

void ether_phy_targets_initialize_vsc8541 (ether_phy_instance_ctrl_t * p_instance_ctrl)
{
                                        ~~ Omission ~~

    /* LED Behavior */
    reg  = ether_phy_read(p_instance_ctrl, ETHER_PHY_REG_LED_BEHAVIOR);
    reg &= ~(1U << ETHER_PHY_REG_LED0_FEATURE_DISABLE_OFFSET);
    reg |= 1U << ETHER_PHY_REG_LED1_FEATURE_DISABLE_OFFSET;
    ether_phy_write(p_instance_ctrl, ETHER_PHY_REG_LED_BEHAVIOR, reg);
#if defined(BOARD_RZN2L_SOM_KIT)  /* for VSC8531 */
    /* select extended page 2 register */
    ether_phy_write(p_instance_ctrl,   ETHER_PHY_REG_EXTEND_GPIO_PAGE, 0x02);

    /* read WoL and MAC Interface Control */
    reg  = ether_phy_read(p_instance_ctrl, 0x1b);

    /* set control to slow */
    reg &= 0xFF9F;
    ether_phy_write(p_instance_ctrl, 0x1b, reg);

    /* Configure RX_CLK delay and TX_CLK delay to 2.0ns */
    ether_phy_write(p_instance_ctrl, ETHER_PHY_REG_EXPAGE2_RGMII_CTRL, 0x0044);

    /* select extended page 0 register */
    ether_phy_write(p_instance_ctrl,   ETHER_PHY_REG_EXTEND_GPIO_PAGE, 0x00);
#endif

}                                       /* End of function ether_phy_targets_initialize() */
```

(4) Add code for nested interrupt.

The following code for nested interrupt should be added to “ethercat_ssc_port_isr_esc_cat” function in rzn/fsp/src/rm_ethercat_ssc_port/rm_ethercat_ssc_port.c.

```
void ethercat_ssc_port_isr_esc_cat (void)
{
    /* Enable nested interrupt. */
    __asm volatile ("cpsie i");
    __asm volatile ("isb");

    ethercat_ssc_port_callback_args_t callback_arg;

    IRQn_Type irq = R_FSP_CurrentIrqGet();
    ethercat_ssc_port_instance_ctrl_t * p_instance_ctrl =
        (ethercat_ssc_port_instance_ctrl_t *) R_FSP_IsrContextGet(irq);

    /* SSC ESC CAT Interrupt handler */
    PDI_Isr();

    /* Callback : Interrupt handler */
    if (NULL != p_instance_ctrl->p_cfg->p_callback)
    {
        callback_arg.event     = ETHERCAT_SSC_PORT_EVENT_ESC_CAT_INTERRUPT;
        callback_arg.p_context = p_instance_ctrl->p_cfg->p_context;

        (*p_instance_ctrl->p_cfg->p_callback)((void *) &callback_arg);
    }

    /* Disable nested interrupt */
    __asm volatile ("cpsid i");
    __asm volatile ("isb");
}                                   /* End of function ethercat_ssc_port_isr_esc_cat() */
```

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Feb 6, 2023	-	First edition issued
1.10	Aug 7, 2023	-	Support RZ/N2L FSP v1.2.0

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)
   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on
   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state
   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins
   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals
   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin
   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses
   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products
   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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